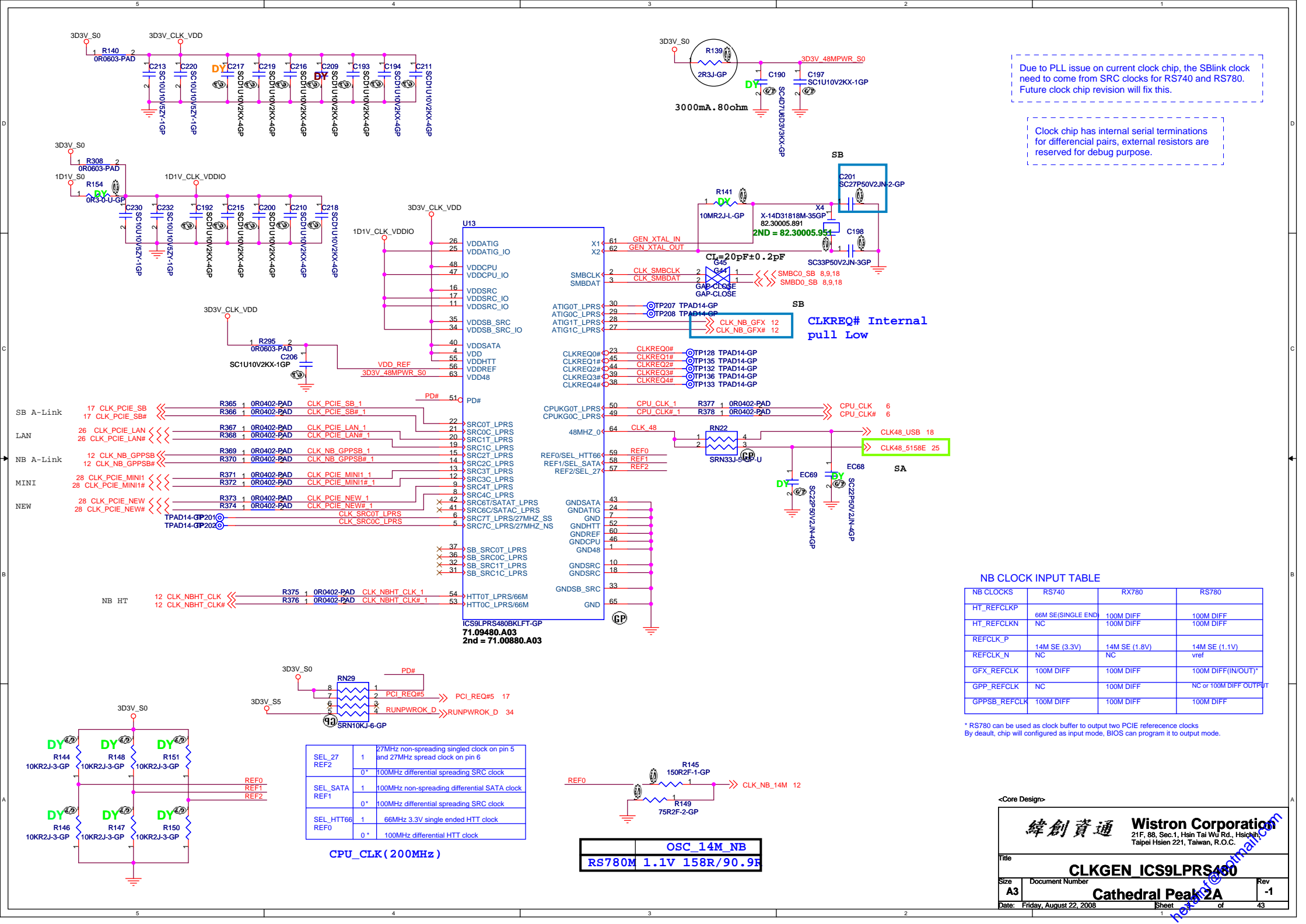


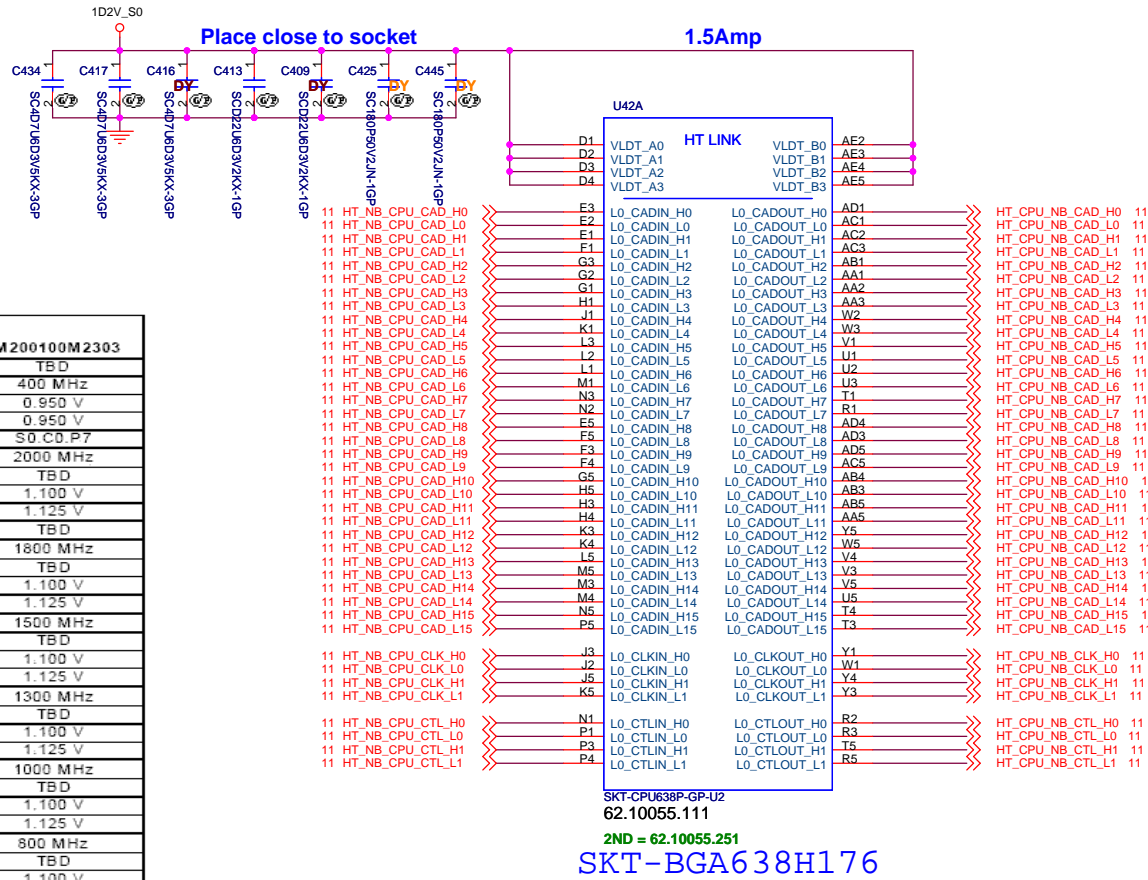
5	4	3	2	1
D				
C				
B				
A				

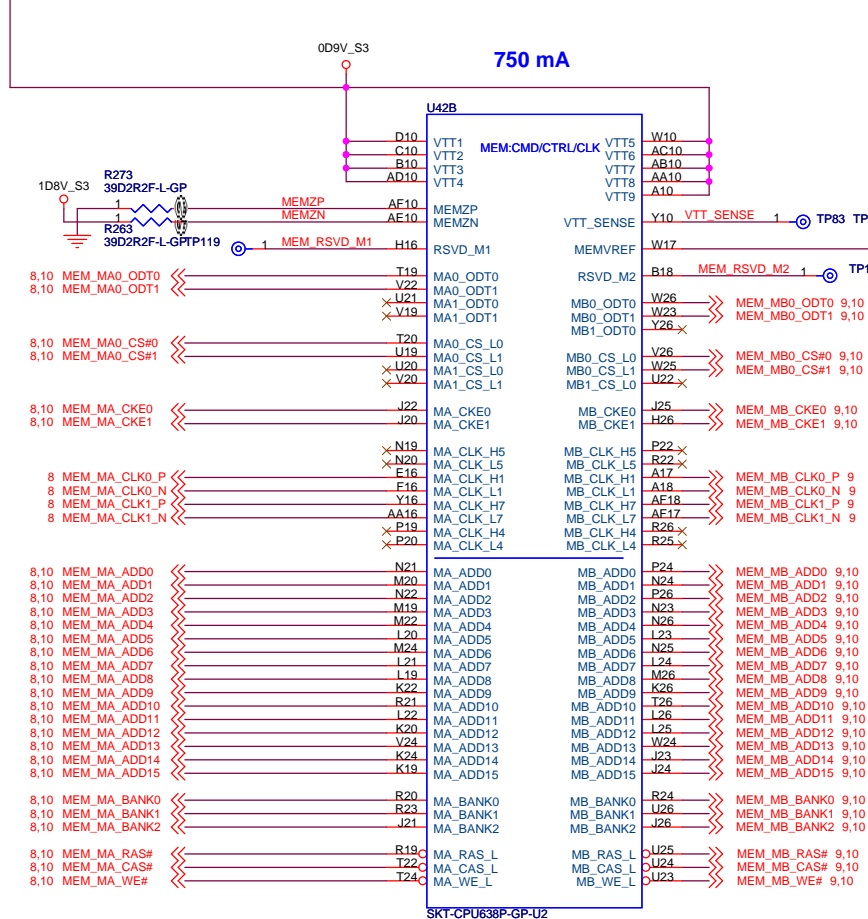
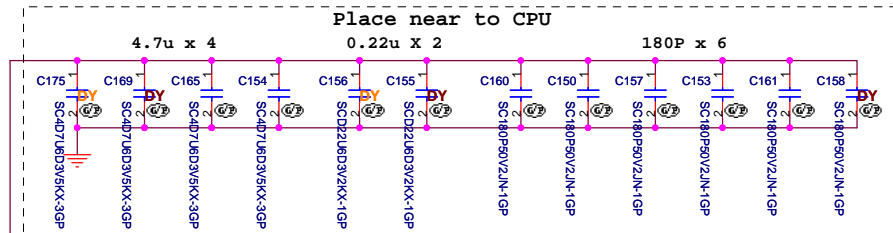
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緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
HISTORY			
Size	Document Number		Rev
A3	Cathedral Peak 2A		-1
Date:	Friday, August 22, 2008		
		Sheet 2 of	43
		1	



State	Specification	Notes	ZM200100M2303
S0.C0.Px	Tcase Max	3	TBD
	NB COF	1	400 MHz
	VID_VDDNB Min	2	0.950 V
	VID_VDDNB Max	2	0.950 V
	Startup P-state		S0.C0.P7
S0.C0.P0	CPU COF	1	2000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	IDD Max	3	TBD
S0.C0.P1	CPU COF	1	1800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1500 MHz
S0.C0.P2	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1300 MHz
	TDP	3	TBD
S0.C0.P3	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	1000 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
S0.C0.P4	VID_VDD Max	2	1.125 V
	CPU COF	1	800 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
S0.C0.P5	CPU COF	1	500 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
S0.C0.P6	TDP	3	TBD
	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
S0.C0.P7	VID_VDD Min	2	1.100 V
	VID_VDD Max	2	1.125 V
	CPU COF	1	300 MHz
	TDP	3	TBD
	VID_VDD Min	2	1.100 V





SKT-CPU638P-GP-U2

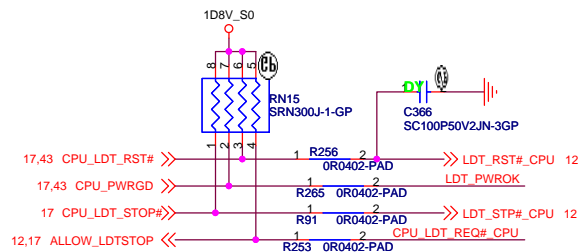


SKT-CPU638P-GP-U2

<Core Design>

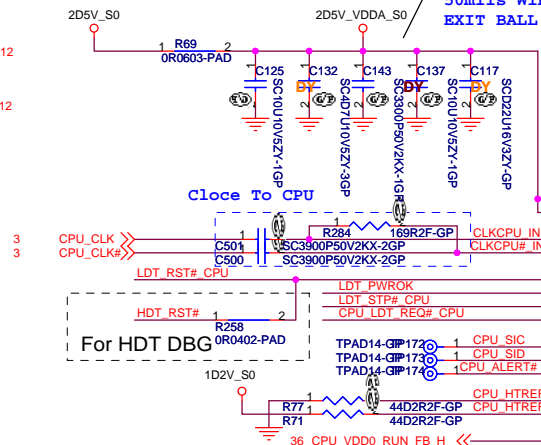
緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichung,
Taipei Hsien 221, Taiwan, R.O.C.

Title CPU DDR (2/4)
Size A3 Document Number Cathedral Peak 2A Rev -1
Date: Friday, August 22, 2008 Sheet 43

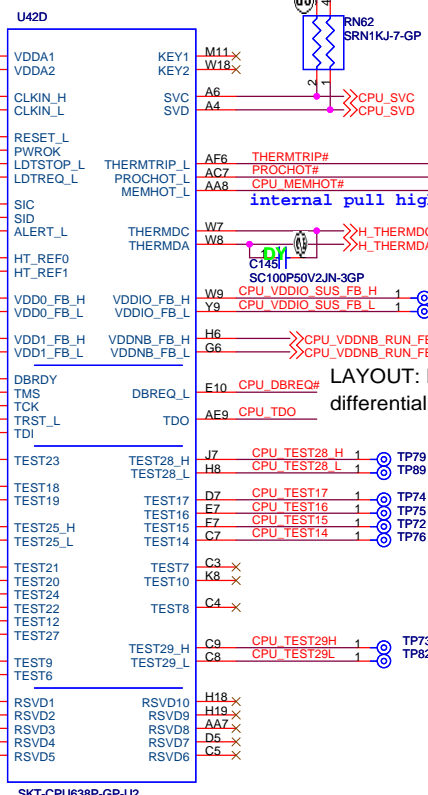
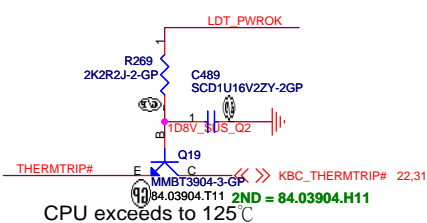
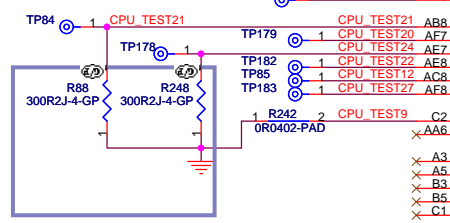
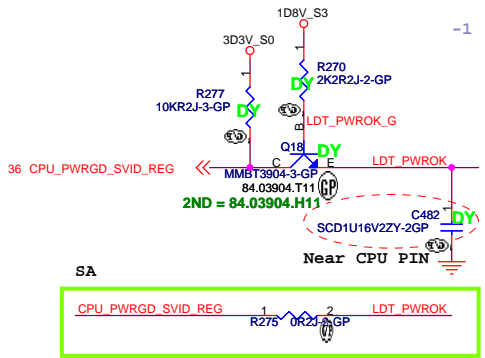


IF 0 ohm IS NOT GOOD ENOUGH, TRY 68.00082.491

LYAOUT:ROUTE VDDA TRACE APPROX.
50mils WIDE(USE 2X25 mil TRACES TO
EXIT BALL FIELD) AND 500 mils LONG.



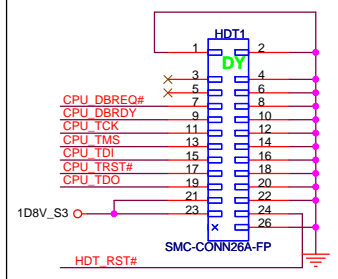
For HDT DBG



LAYOUT: Route FBCLKOUT_H/L
differentially impedance 80

The Processor has
reached a preset
maximum operating
temperature. 100°C
I=Active HTC
O=FAN

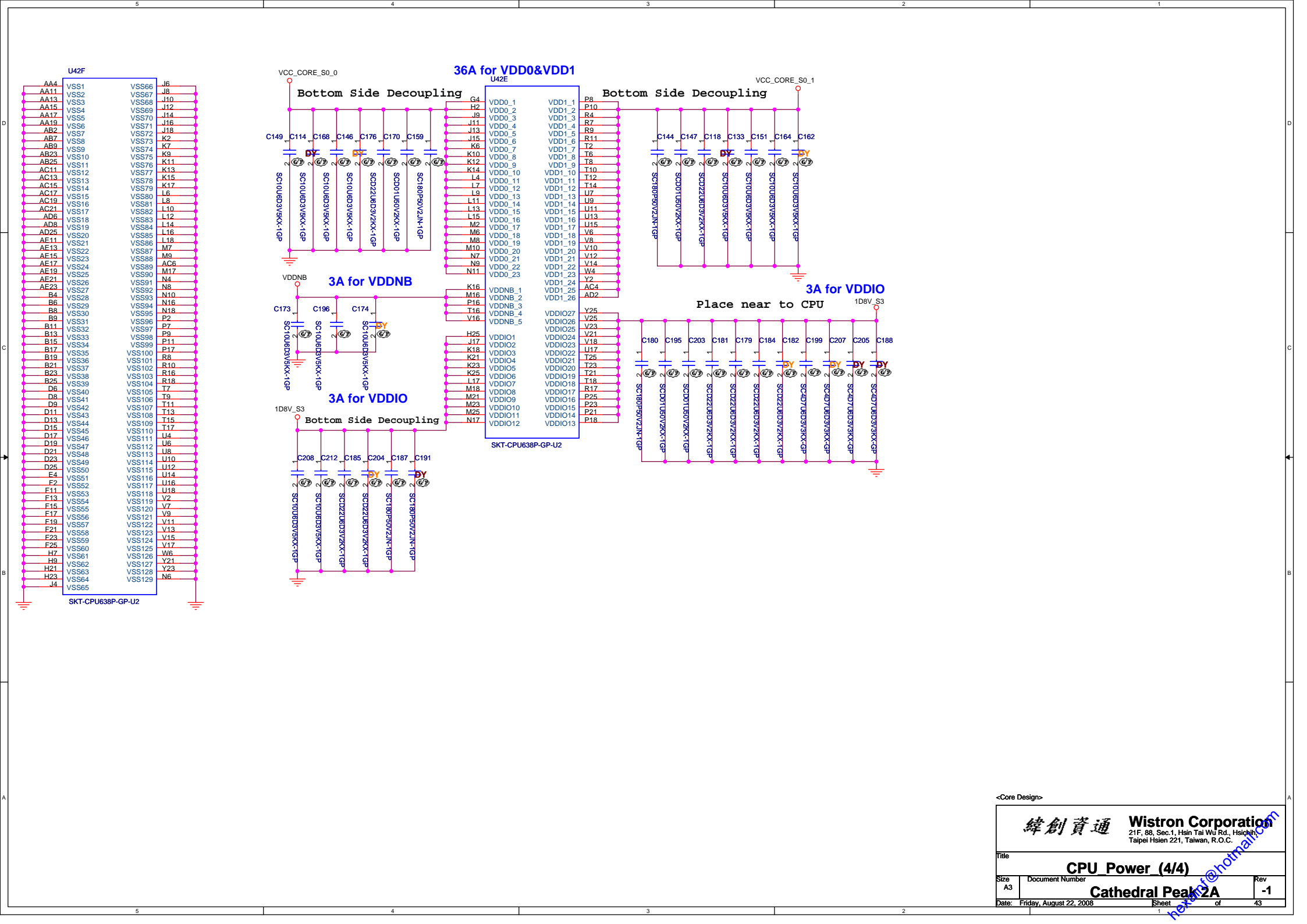
HDT Connectors



<Core Design>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin,
Taipei Hsien 221, Taiwan, R.O.C.

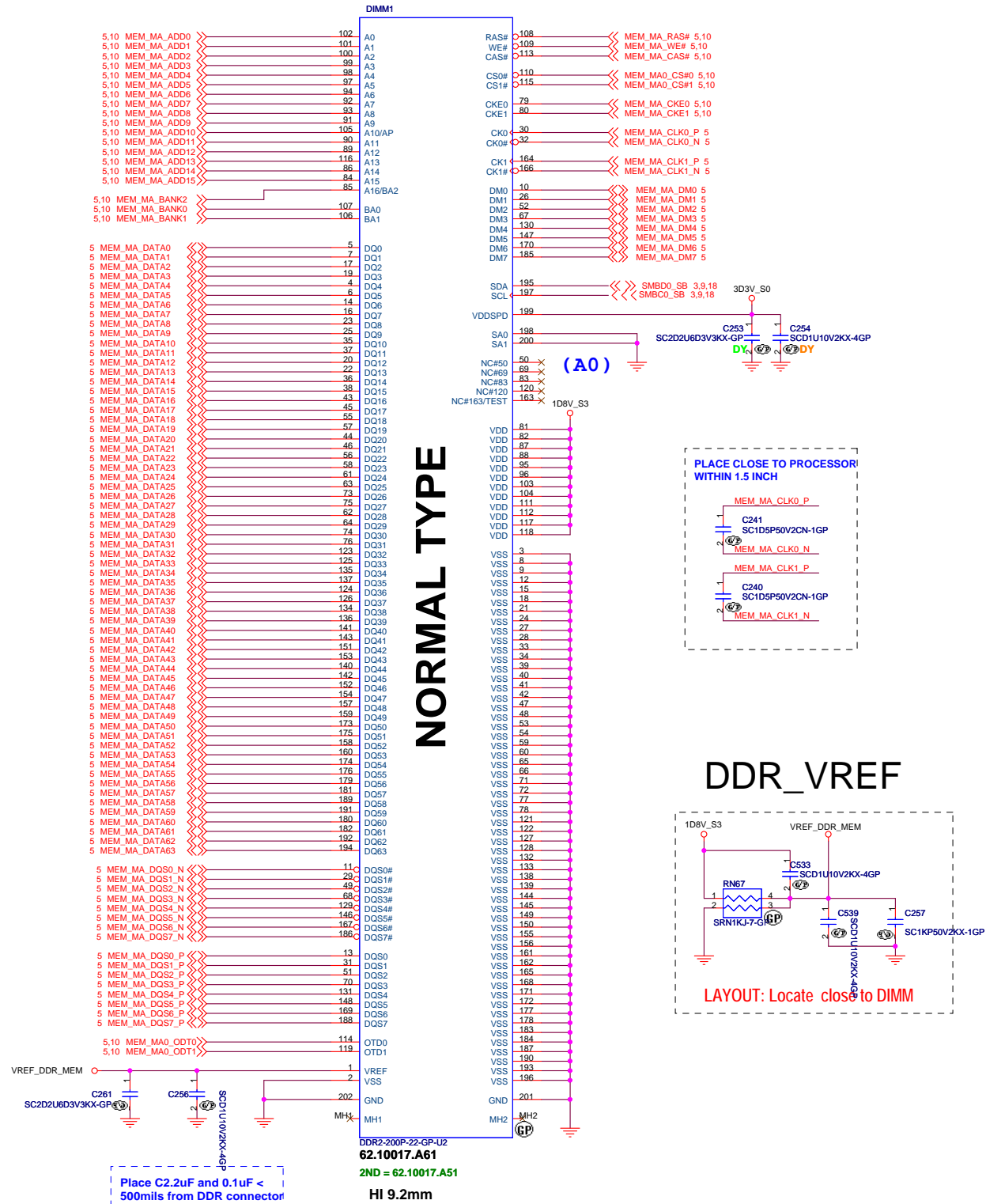
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Size	Document Number	Rev		
A3		Cathedral Peak 2A		-1
Date:	Friday, August 22, 2008	Sheet	6	of 43



<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

Title			CPU Power (4/4)
Size	Document Number	Rev	
A3		Cathedral Peak 2A	
Date: Friday, August 22, 2008		Sheet	43
		of	-1



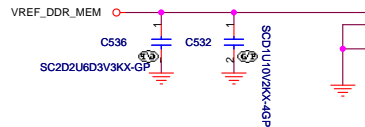
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5,10 MEM_MB_ADD0 >> 102
5,10 MEM_MB_ADD1 >> 101
5,10 MEM_MB_ADD2 >> 100
5,10 MEM_MB_ADD3 >> 99
5,10 MEM_MB_ADD4 >> 98
5,10 MEM_MB_ADD5 >> 97
5,10 MEM_MB_ADD6 >> 96
5,10 MEM_MB_ADD7 >> 95
5,10 MEM_MB_ADD8 >> 94
5,10 MEM_MB_ADD9 >> 93
5,10 MEM_MB_ADD10 >> 92
5,10 MEM_MB_ADD11 >> 91
5,10 MEM_MB_ADD12 >> 90
5,10 MEM_MB_ADD13 >> 89
5,10 MEM_MB_ADD14 >> 88
5,10 MEM_MB_ADD15 >> 87
5,10 MEM_MB_BANK2 >> 107
5,10 MEM_MB_BANK0 >> 106
5,10 MEM_MB_BANK1 >> 105

5 MEM_MB_DATA0 >> 5
5 MEM_MB_DATA1 >> 7
5 MEM_MB_DATA2 >> 17
5 MEM_MB_DATA3 >> 19
5 MEM_MB_DATA4 >> 4
5 MEM_MB_DATA5 >> 6
5 MEM_MB_DATA6 >> 14
5 MEM_MB_DATA7 >> 16
5 MEM_MB_DATA8 >> 23
5 MEM_MB_DATA9 >> 25
5 MEM_MB_DATA10 >> 35
5 MEM_MB_DATA11 >> 37
5 MEM_MB_DATA12 >> 20
5 MEM_MB_DATA13 >> 22
5 MEM_MB_DATA14 >> 36
5 MEM_MB_DATA15 >> 38
5 MEM_MB_DATA16 >> 43
5 MEM_MB_DATA17 >> 45
5 MEM_MB_DATA18 >> 55
5 MEM_MB_DATA19 >> 57
5 MEM_MB_DATA20 >> 44
5 MEM_MB_DATA21 >> 46
5 MEM_MB_DATA22 >> 58
5 MEM_MB_DATA23 >> 58
5 MEM_MB_DATA24 >> 61
5 MEM_MB_DATA25 >> 63
5 MEM_MB_DATA26 >> 73
5 MEM_MB_DATA27 >> 75
5 MEM_MB_DATA28 >> 62
5 MEM_MB_DATA29 >> 64
5 MEM_MB_DATA30 >> 74
5 MEM_MB_DATA31 >> 76
5 MEM_MB_DATA32 >> 123
5 MEM_MB_DATA33 >> 125
5 MEM_MB_DATA34 >> 135
5 MEM_MB_DATA35 >> 137
5 MEM_MB_DATA36 >> 124
5 MEM_MB_DATA37 >> 126
5 MEM_MB_DATA38 >> 134
5 MEM_MB_DATA39 >> 136
5 MEM_MB_DATA40 >> 141
5 MEM_MB_DATA41 >> 143
5 MEM_MB_DATA42 >> 151
5 MEM_MB_DATA43 >> 153
5 MEM_MB_DATA44 >> 140
5 MEM_MB_DATA45 >> 142
5 MEM_MB_DATA46 >> 152
5 MEM_MB_DATA47 >> 154
5 MEM_MB_DATA48 >> 157
5 MEM_MB_DATA49 >> 159
5 MEM_MB_DATA50 >> 173
5 MEM_MB_DATA51 >> 175
5 MEM_MB_DATA52 >> 158
5 MEM_MB_DATA53 >> 160
5 MEM_MB_DATA54 >> 174
5 MEM_MB_DATA55 >> 176
5 MEM_MB_DATA56 >> 179
5 MEM_MB_DATA57 >> 181
5 MEM_MB_DATA58 >> 189
5 MEM_MB_DATA59 >> 191
5 MEM_MB_DATA60 >> 180
5 MEM_MB_DATA61 >> 182
5 MEM_MB_DATA62 >> 192
5 MEM_MB_DATA63 >> 194

5 MEM_MB_DQS0_N >> 110
5 MEM_MB_DQS1_N >> 29
5 MEM_MB_DQS2_N >> 49
5 MEM_MB_DQS3_N >> 68
5 MEM_MB_DQS4_N >> 129
5 MEM_MB_DQS5_N >> 146
5 MEM_MB_DQS6_N >> 167
5 MEM_MB_DQS7_N >> 186
5 MEM_MB_DQS0_P >> 13
5 MEM_MB_DQS1_P >> 31
5 MEM_MB_DQS2_P >> 51
5 MEM_MB_DQS3_P >> 70
5 MEM_MB_DQS4_P >> 131
5 MEM_MB_DQS5_P >> 148
5 MEM_MB_DQS6_P >> 169
5 MEM_MB_DQS7_P >> 188

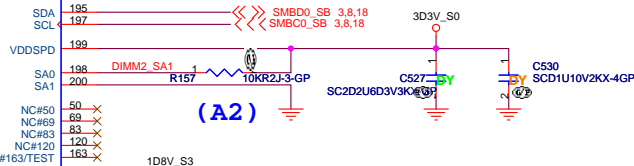
5,10 MEM_MB_ODT0 >> 114
5,10 MEM_MB_ODT1 >> 119



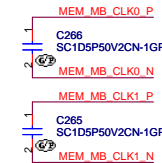
Place C2.2uF and 0.1uF < 500mils from DDR connector

REVERSE TYPE

RAS# 108
WE# 109
CAS# 113
CS0# 110
CS1# 115
CKE0 79
CKE1 80
CK0 30
CK0# 32
CK1 164
CK1# 166
DM0 10
DM1 26
DM2 52
DM3 67
DM4 130
DM5 147
DM6 170
DM7 185
SDA 195
SCL 197
VDDSPD 199
SA0 198
SA1 200
NC#50 50
NC#69 69
NC#83 83
NC#120 120
NC#163/TEST 163
VDD 81
VDD 82
VDD 87
VDD 88
VDD 95
VDD 96
VDD 103
VDD 104
VDD 111
VDD 112
VDD 117
VDD 118
VSS 3
VSS 8
VSS 9
VSS 12
VSS 15
VSS 18
VSS 21
VSS 24
VSS 27
VSS 28
VSS 33
VSS 34
VSS 38
VSS 40
VSS 41
VSS 42
VSS 47
VSS 48
VSS 49
VSS 53
VSS 54
VSS 59
VSS 60
VSS 65
VSS 66
VSS 71
VSS 72
VSS 77
VSS 78
VSS 121
VSS 122
VSS 127
VSS 128
VSS 132
VSS 133
VSS 138
VSS 139
VSS 144
VSS 145
VSS 149
VSS 150
VSS 155
VSS 156
VSS 161
VSS 162
VSS 165
VSS 168
VSS 171
VSS 172
VSS 177
VSS 178
VSS 183
VSS 184
VSS 187
VSS 190
VSS 193
VSS 196
GND 201
MH2 GP



PLACE CLOSE TO PROCESSOR
WITHIN 1.5 INCH



SKT-SODIMM20020U3GP
62.10017.661

2ND = 62.10017.A41

LOW 5.2 mm

<Core Design>

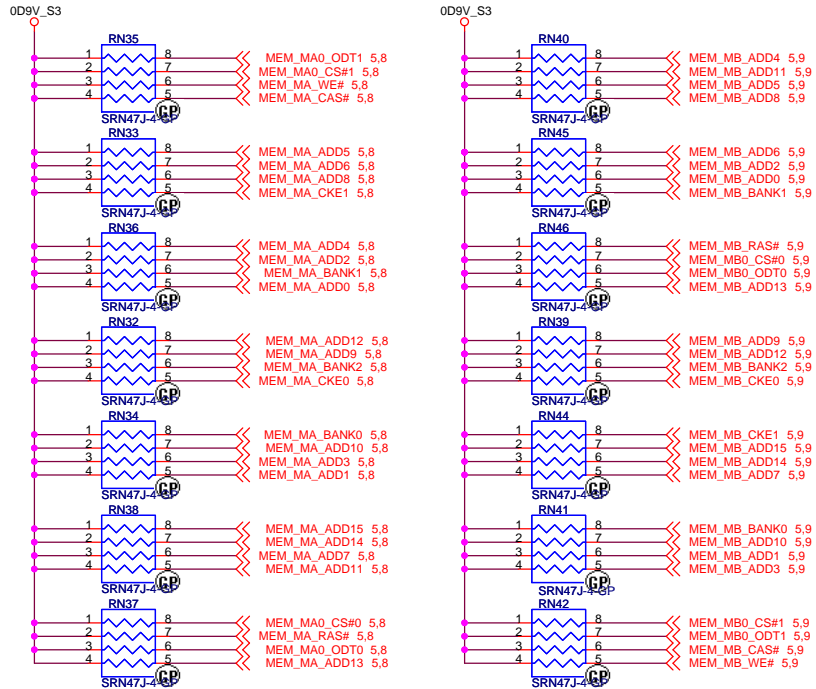
緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsinchu,
Taippei Hsien 221, Taiwan, R.O.C.

Title			
DDR SO-DIMM SKT 2			
Size	Document Number	Rev	
Custom			-1
Cathedral Peak 2A			
Date: Friday, August 22, 2008	Sheet 9	of	43

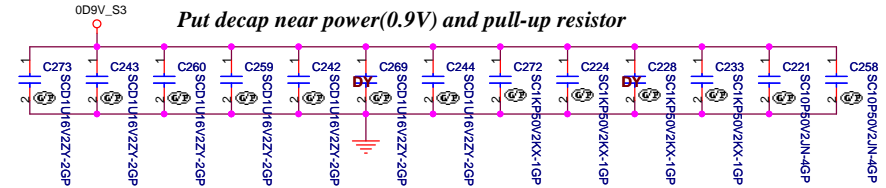
PARALLEL TERMINATION

Put decap near power(0.9V) and pull-up resistor

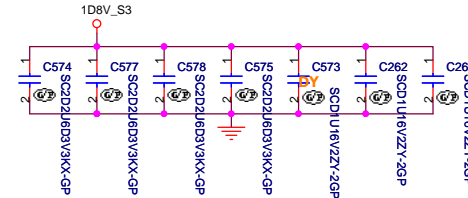


Do not share the Term resistor between the DDR address and Control Signals.

Decoupling Capacitor

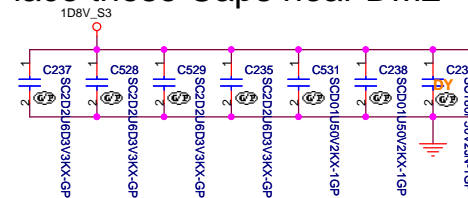


Place these Caps near DM1

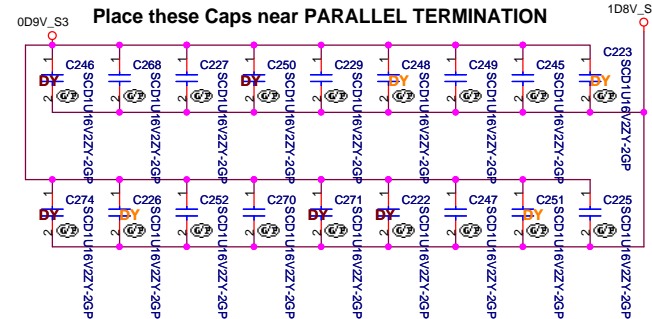


Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3

Place these Caps near DM2



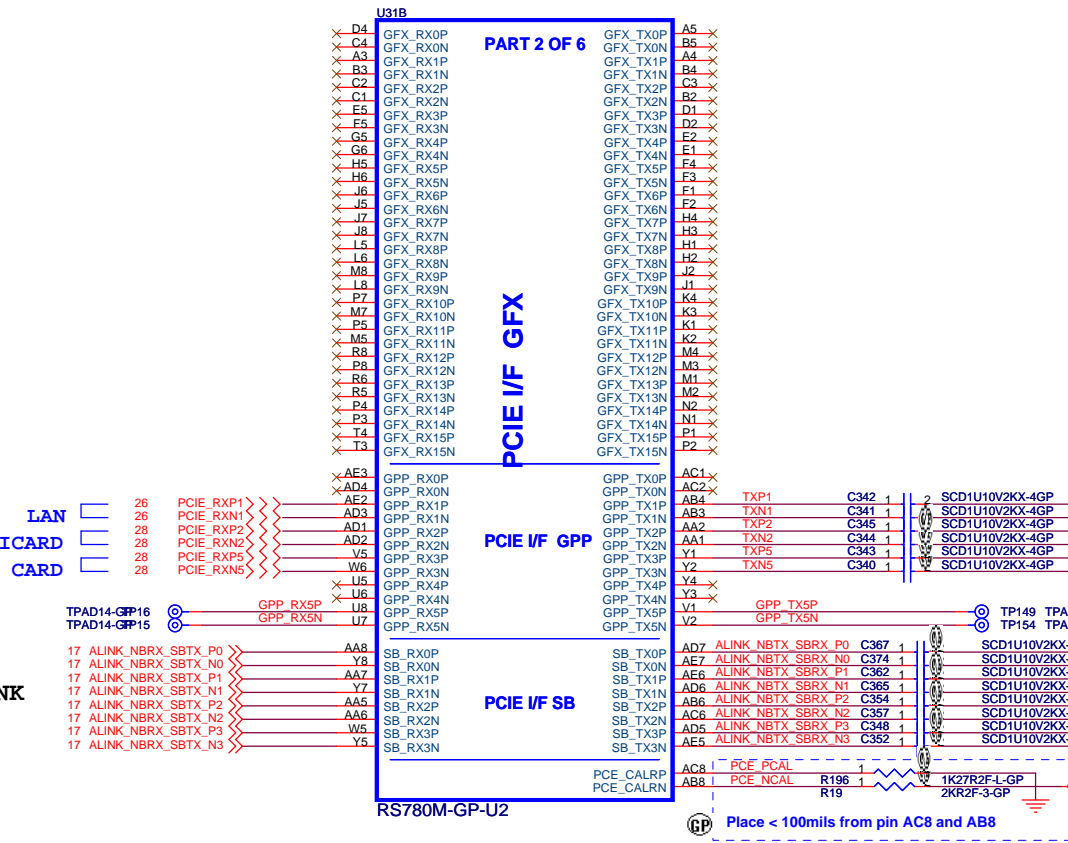
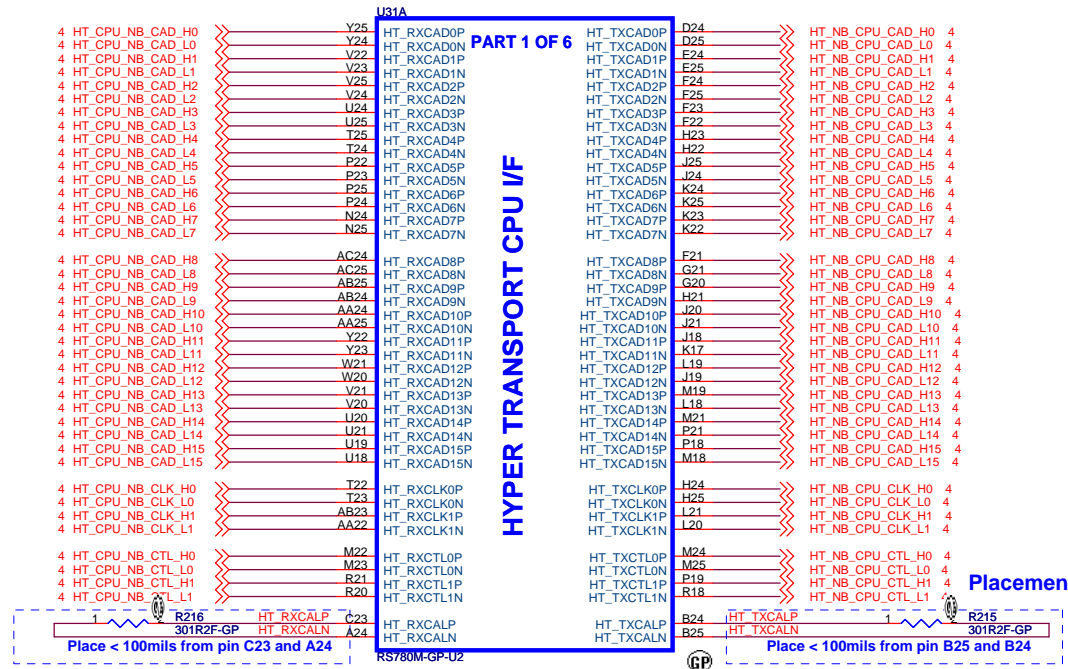
Layout Note:
Place one cap close to every 2 pullup resistors terminated to 0D9V_S3



<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

Title			DDR DAMPING & TERMINATION
Size	Document Number	Rev	
A3		-1	
Date: Friday, August 22, 2008			Sheet 10 of 43



RS780M Display Port Support(muxed on GFX)

DP0	GFX_TX0, TX1, TX2, TX3, AUX0, HPD0
DP1	GFX_TX4, TX5, TX6, TX7, AUX1, HPD1

偉創資通 Wistron Corporation

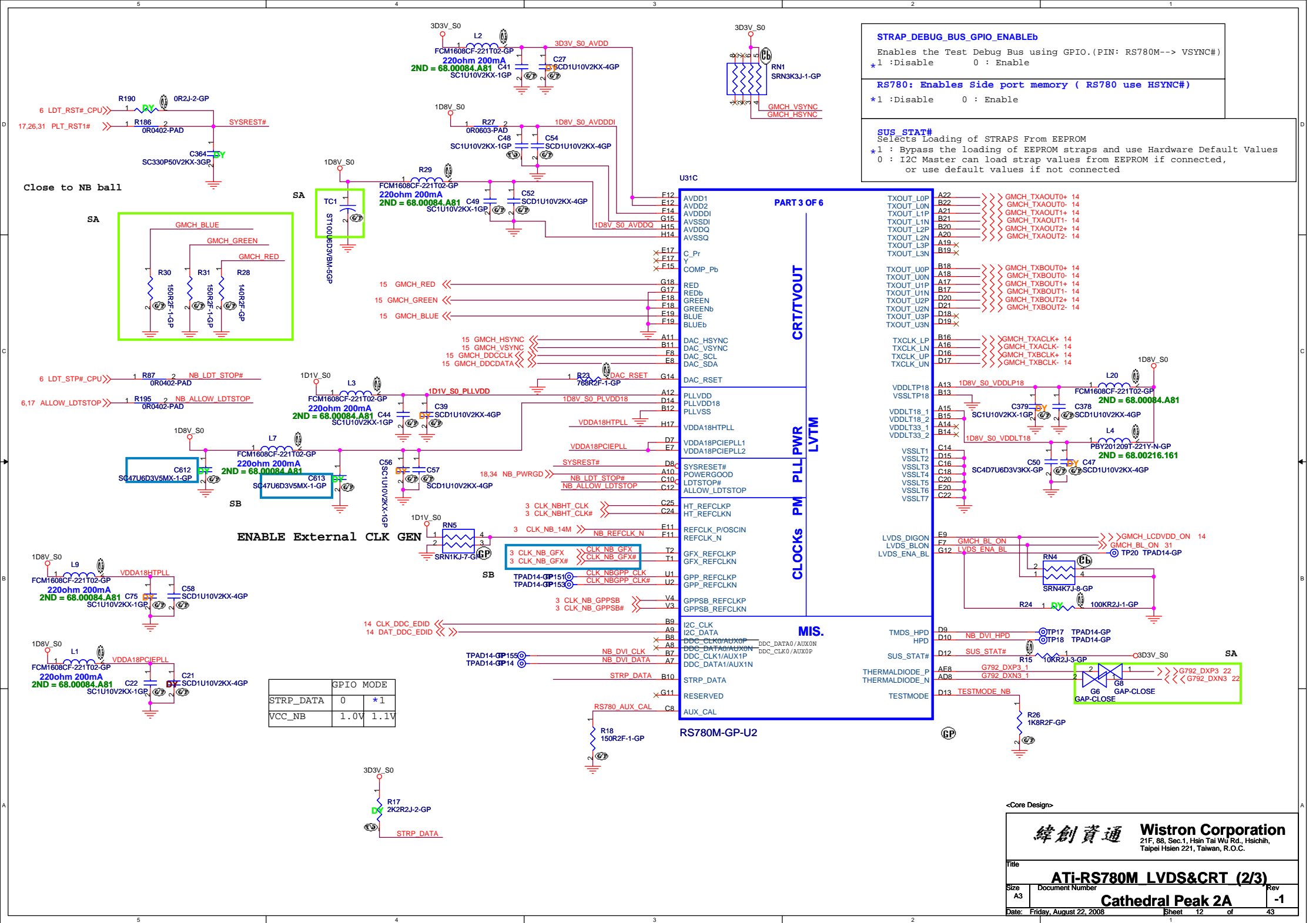
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

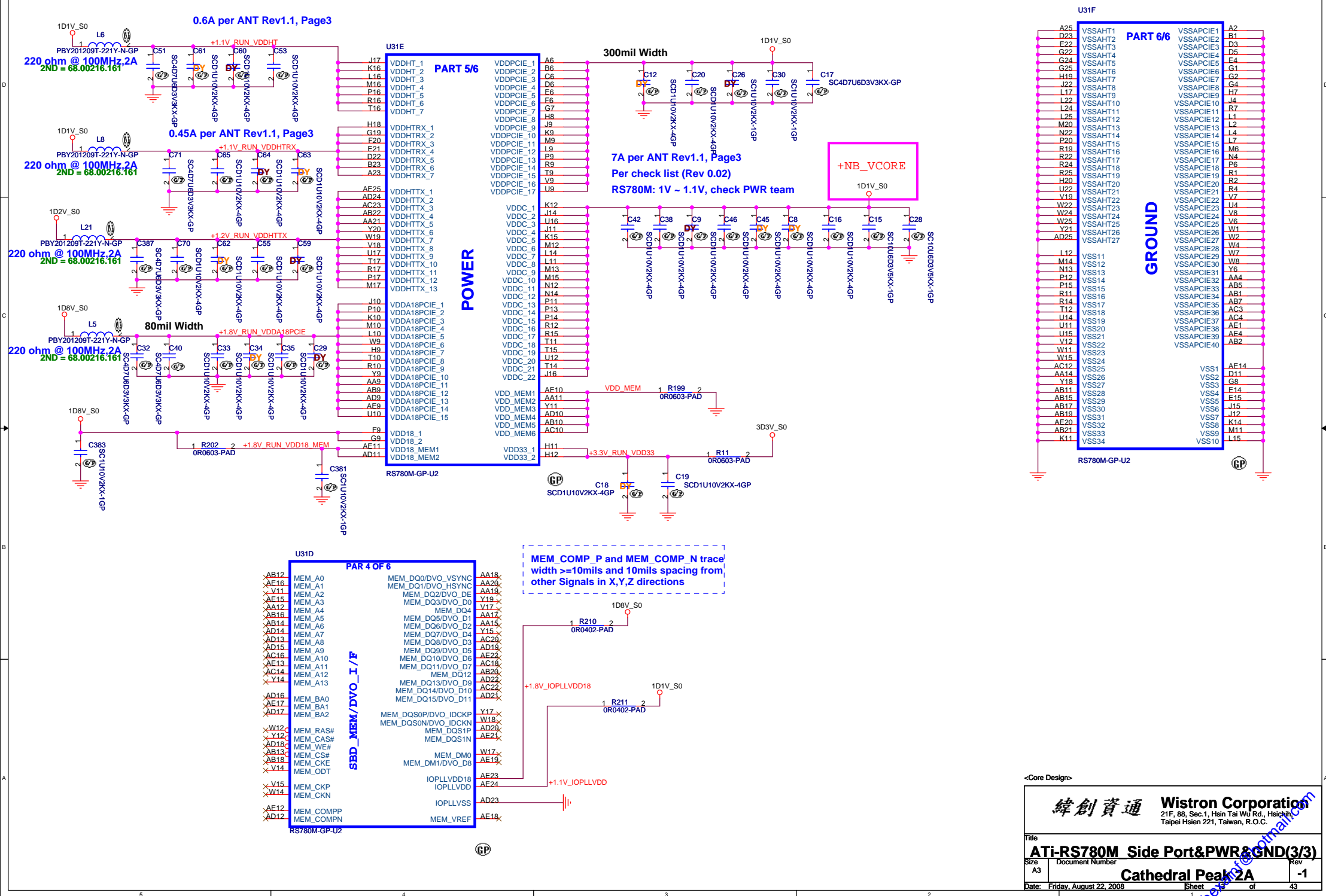
ATI-RS780M HT LINK&PCIE(1/3)

Cathedral Peak 2A

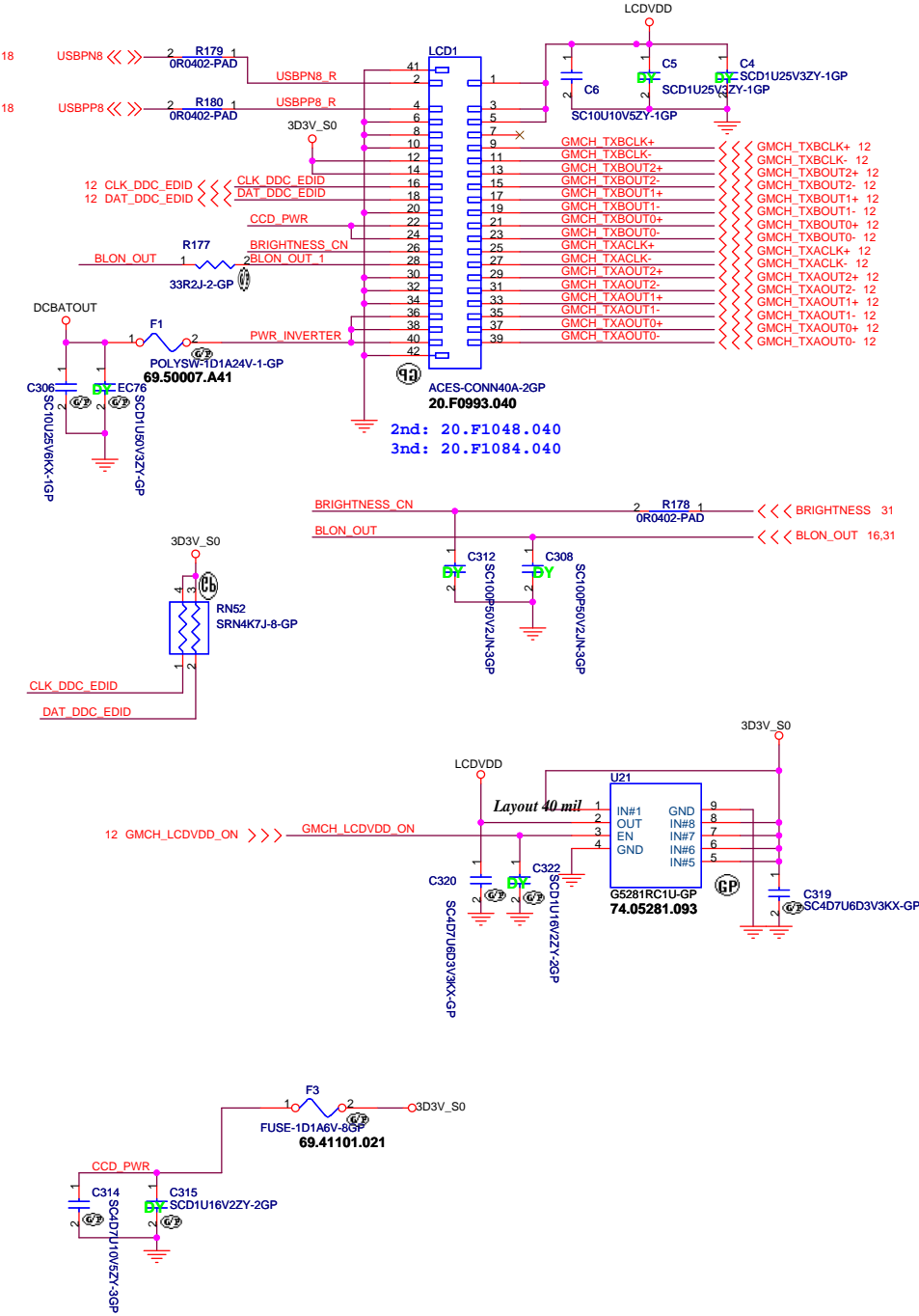
Rev -1

Sheet 43

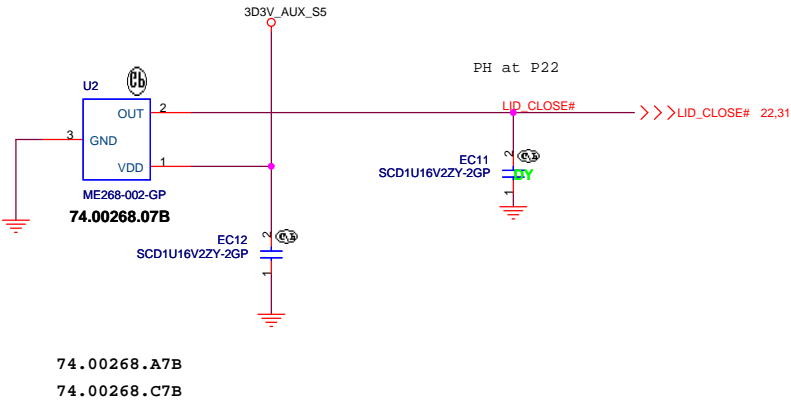




LCD/INVERTER/CCD CONN



Cover Up Switch

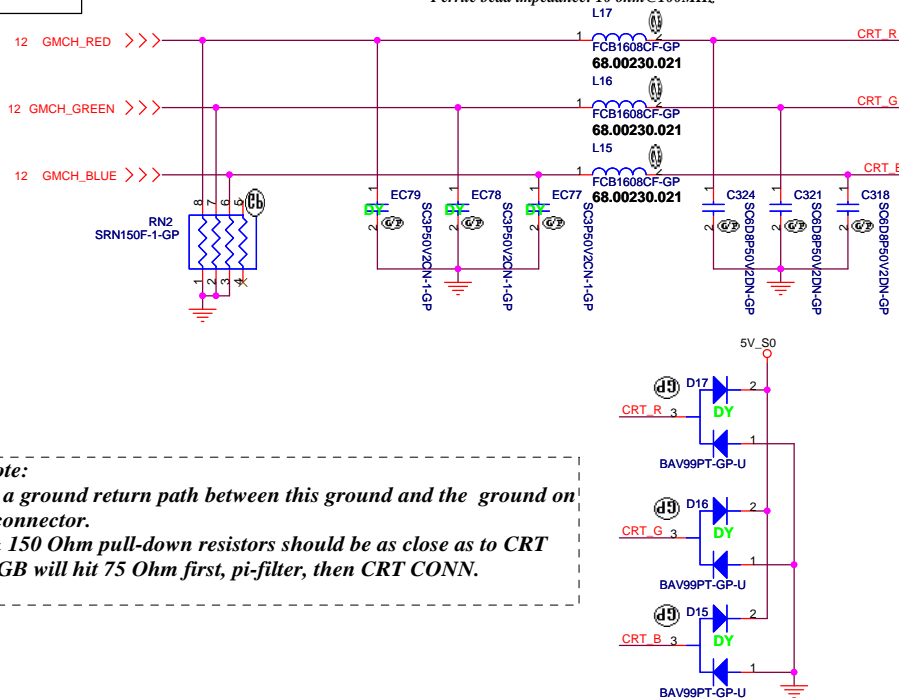


Inverter Pin	
Pin	Symbol
1	Vin
2	Vin
3	Brightness
4	BLON
5	GND
6	GND

CCD Pin	
Pin	Symbol
1	CCD_PWR
2	USB-
3	USB+
4	GND
5	GND

Layout Note:
Place these resistors
close to the CRT-out
connector

Ferrite bead impedance: 10 ohm@100MHz

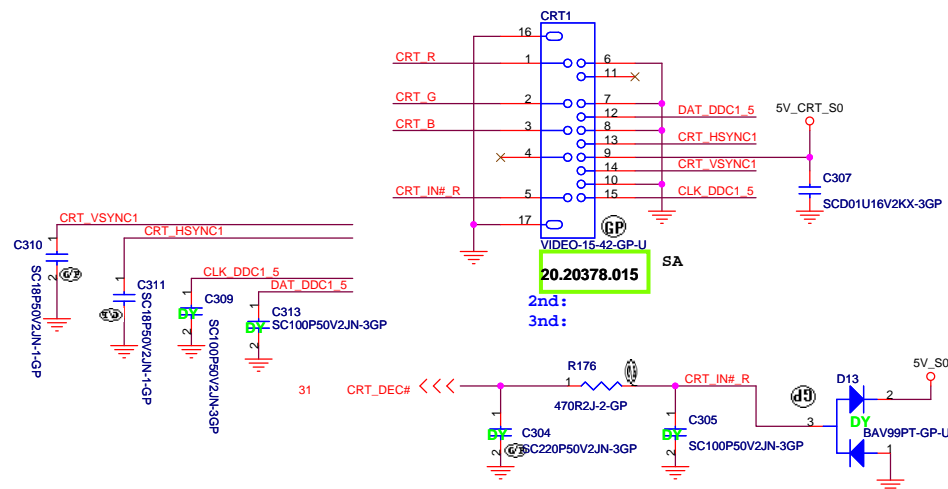


Layout Note:

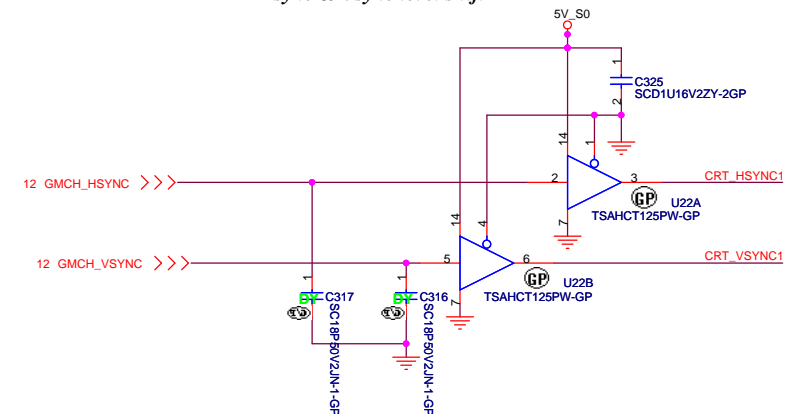
* Must be a ground return path between this ground and the ground on the VGA connector.

Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.

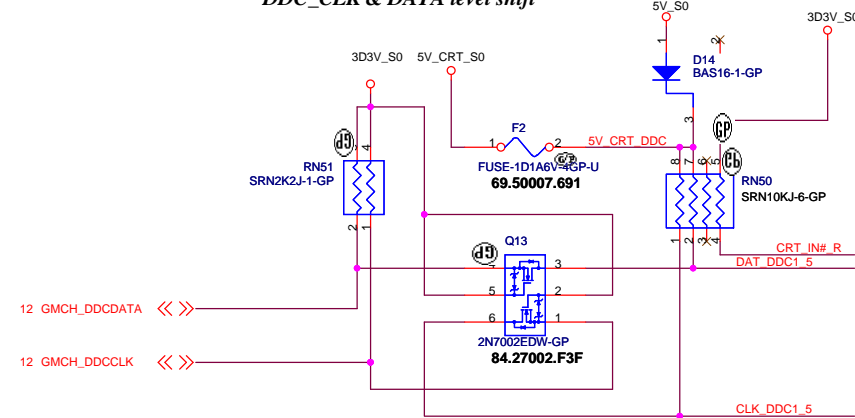
CRT I/F & CONNECTOR



Hsync & Vsync level shift



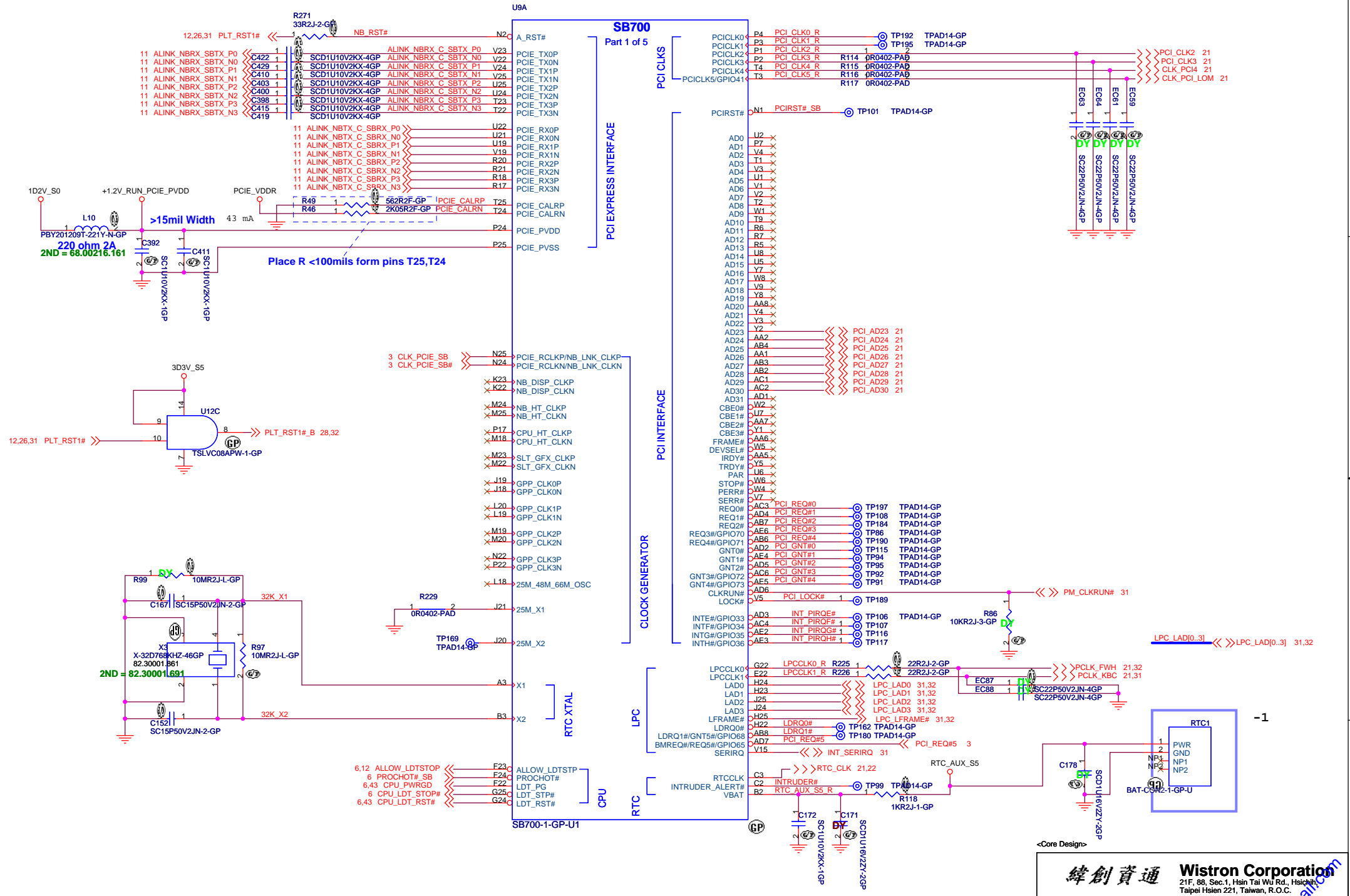
DDC_CLK & DATA level shift



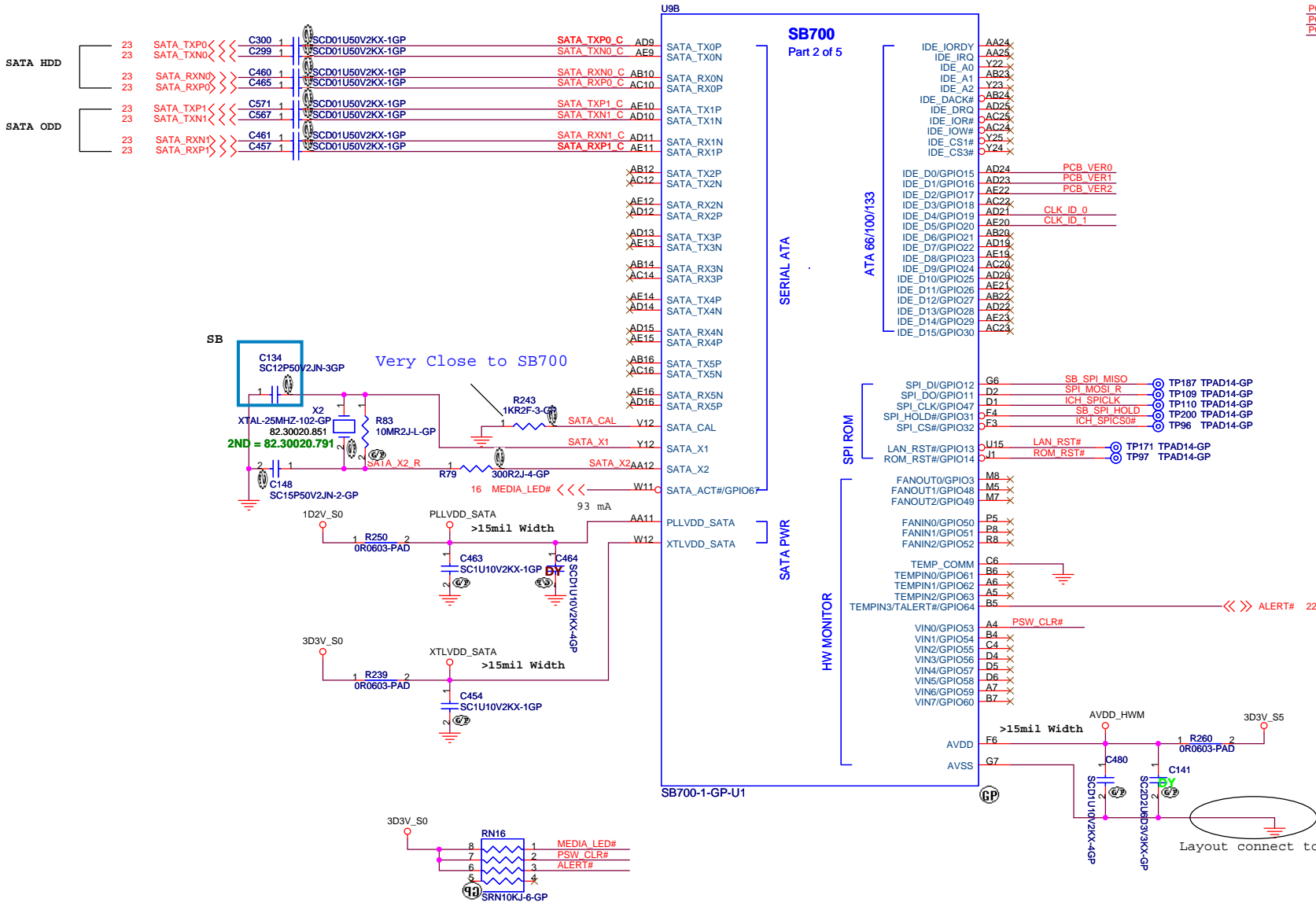
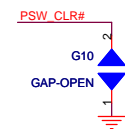
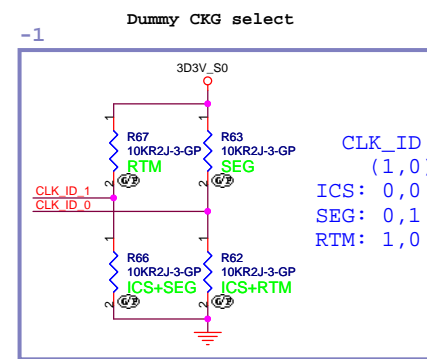
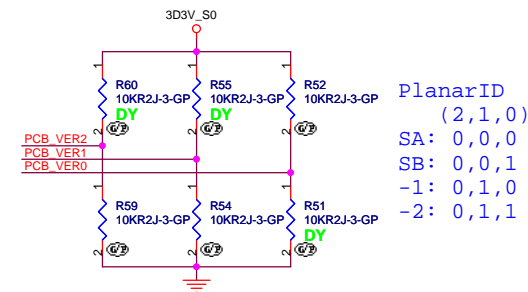
<Core Design>

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title: CRT Connector			
Size	Document Number	Rev	
Date: Friday, August 22, 2008		Sheet 15 of 43	-1



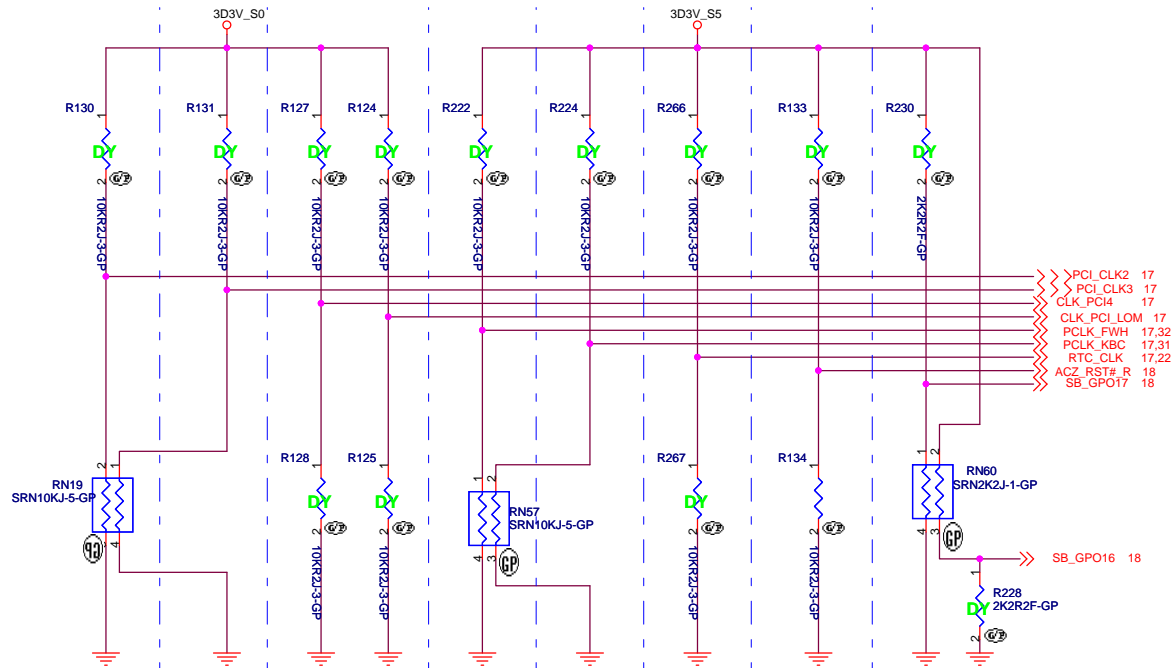


PLACE SATA AC DECOUPLING
CAPS CLOSE TO SB700

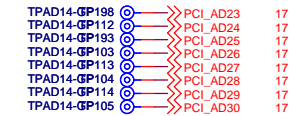


REQUIRED STRAPS

REQUIRED SYSTEM STRAPS



DEBUG STRAPS



	PCI_CLK2	PCI_CLK3	CLK_PCI_LOM CLK_PCI4	PCLK_FWH	PCLK_KBC	RTCCLK	AZ_RST#	SB_GPO17, SB_GPO16
PULL HIGH	WatchDOG (NB_PWRGD) ENABLED	USE DEBUG STRAPS	RESERVED	IMC ENABLED	CLKGEN ENABLED (Use Internal)	INTERNAL RTC DEFAULT	ENABLE PCI ROM BOOT	ROM TYPE: H, H = Reserved H, L = SPI ROM DEFAULT
PULL LOW	WatchDog (NB_PWRGD) DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT		IMC DISABLED DEFAULT	CLKGEN DISABLED (Use External) DEFAULT	EXT. RTC (PD on X1, apply 32KHz to RTC_CLK)	DISABLE PCI ROM BOOT DEFAULT	L, H = LPC ROM L, L = FWH ROM

NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTCCLK

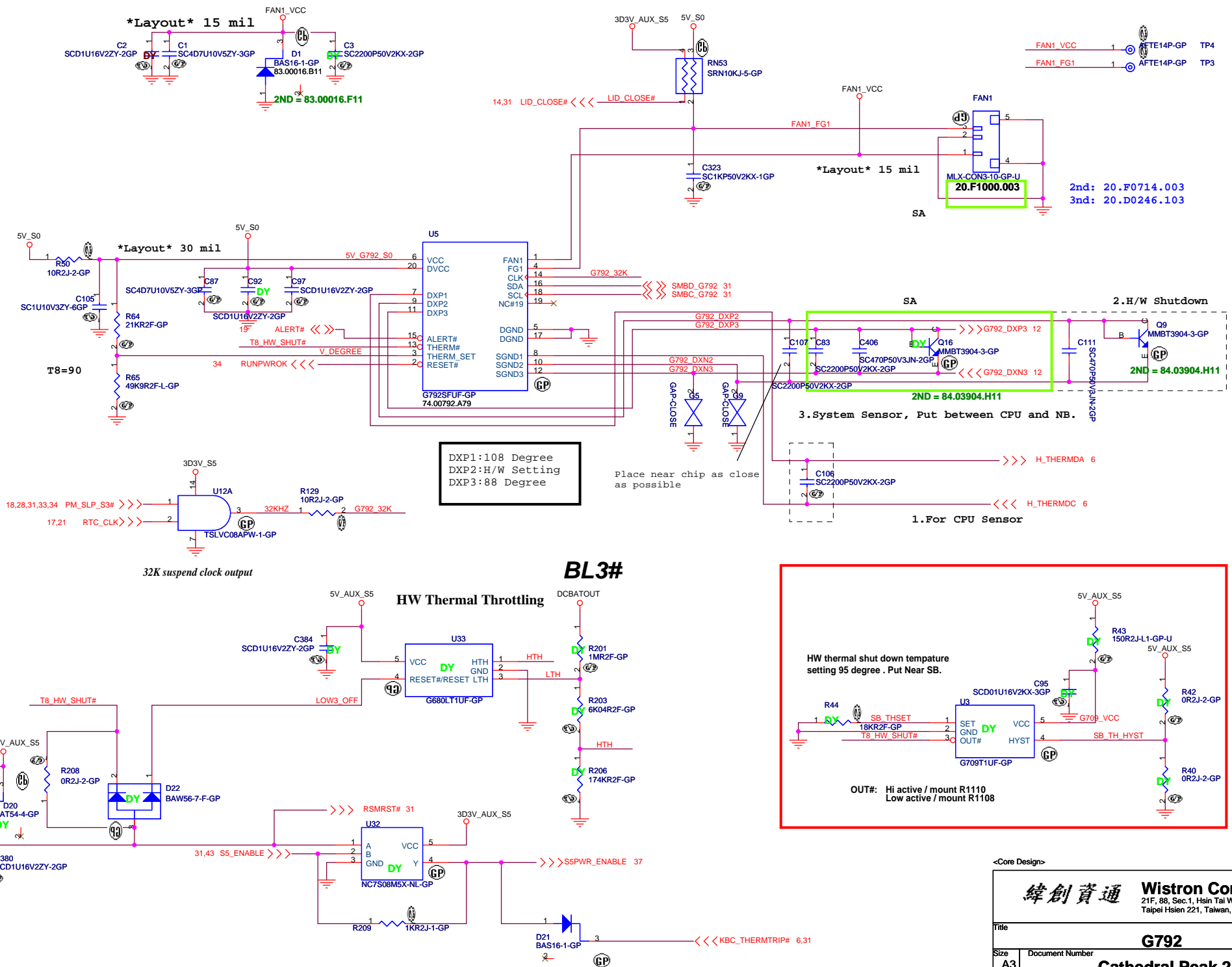
	PCI_AD28	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23	PCI_AD30 PCI_AD29
PULL HIGH	USE LONG RESET (DEFAULT)	USE PCI PLL (DEFAULT)	USE ACPI BCLK (DEFAULT)	USE IDE PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Reserved (DEFAULT)	Reserved
PULL LOW	USE SHORT RESET	BYPASS PCI PLL	BYPASS ACPI BCLK	BYPASS IDE PLL	USE EEPROM PCIE STRAPS	Reserved	

Note: SB700 has 15K internal PU FOR PCI_AD[30:23]

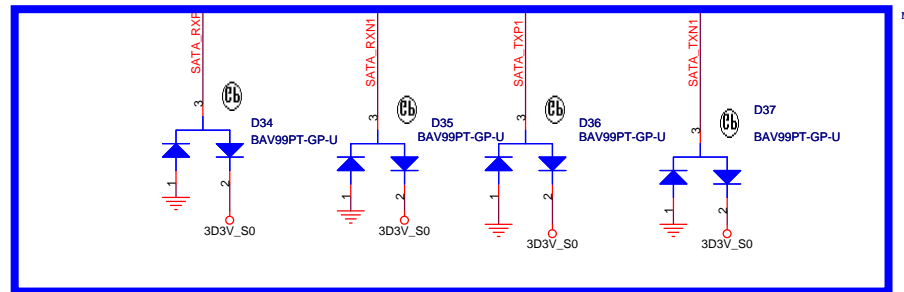
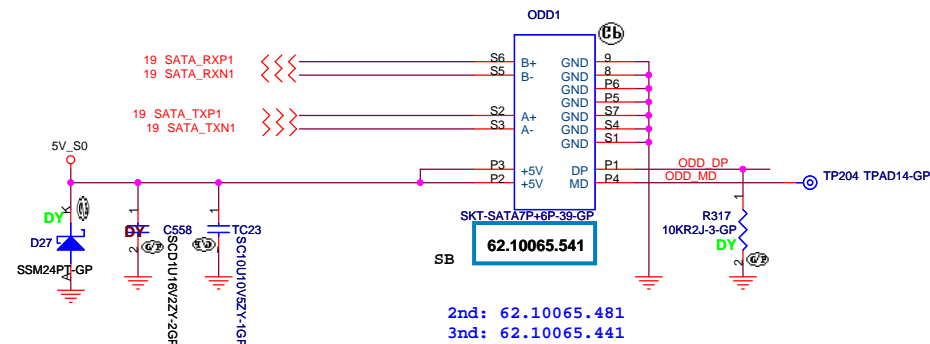
<Core Design>

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin,
Taipei Hsien 221, Taiwan, R.O.C.

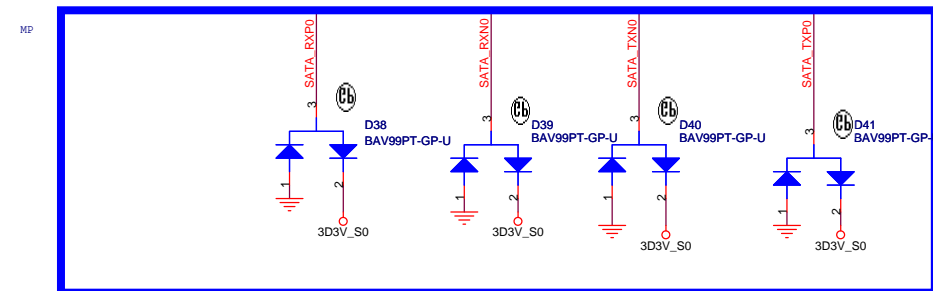
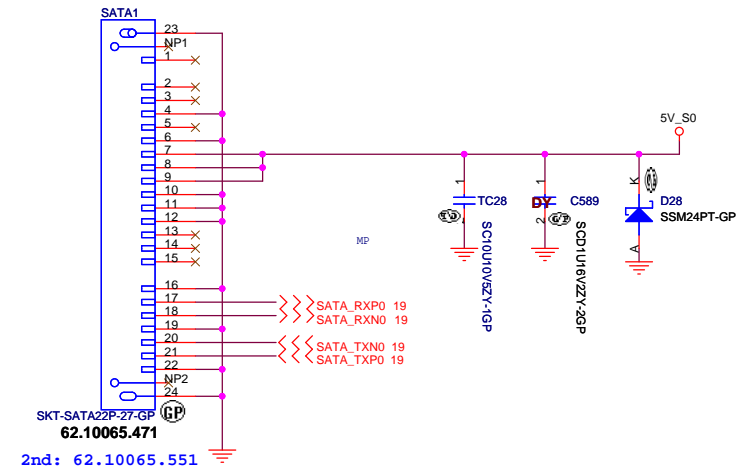
Title			
ATI-SB700 STRAPPING (5/5)			
Size	Document Number		Rev
A3	Cathedral Peak 2A		-1
Date:	Friday, August 22, 2008	Sheet 21 of 43	



SATA ODD Connector



SATA Connector



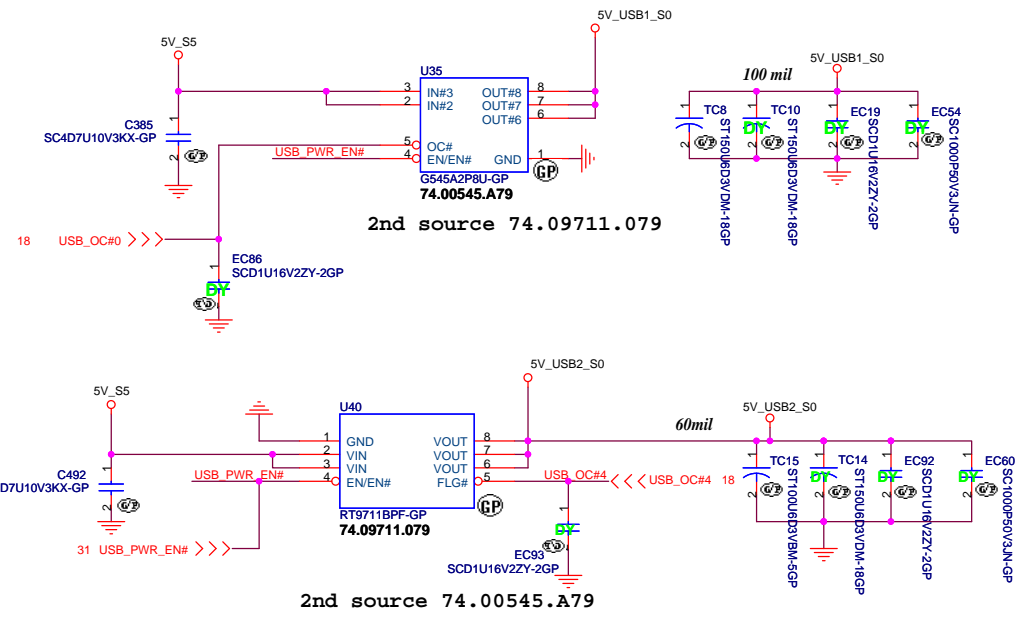
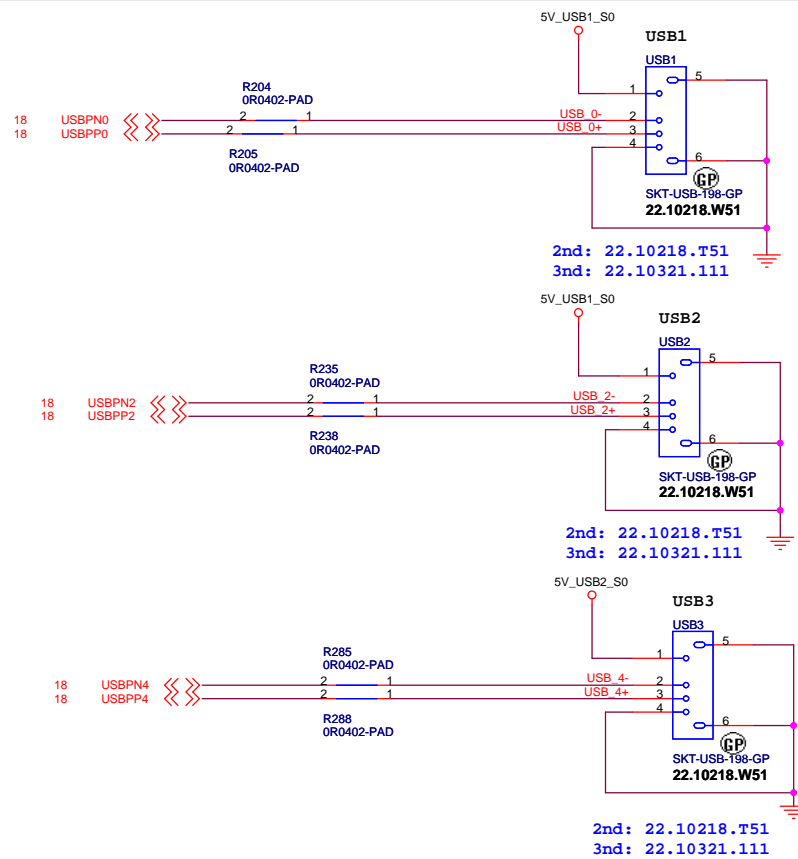
<Core Design>

緯創資通

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Taipai Hsien 221, Taiwan, R.O.C.

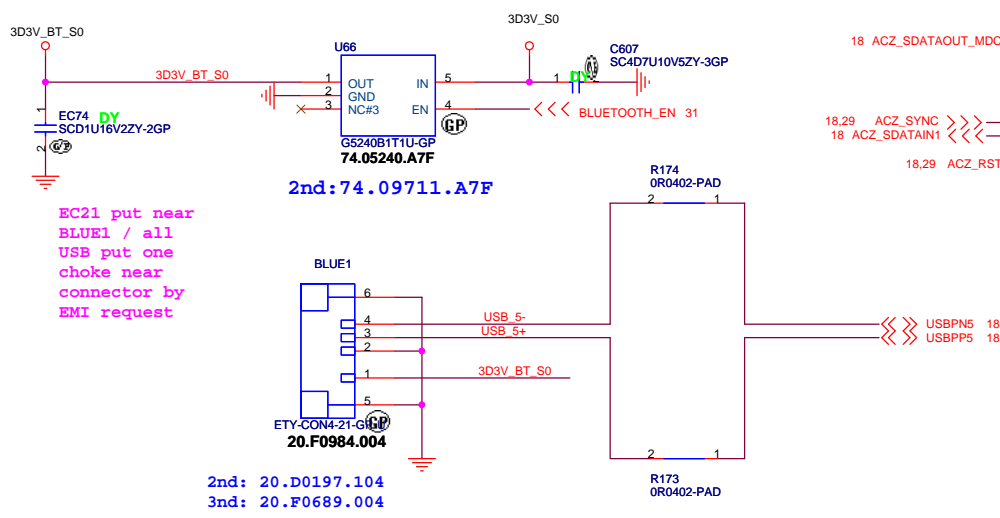
Title			HDD & CDROM
Size	Document Number	Rev	-1
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Cathedral Peak 2A

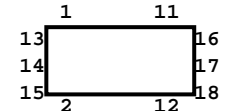
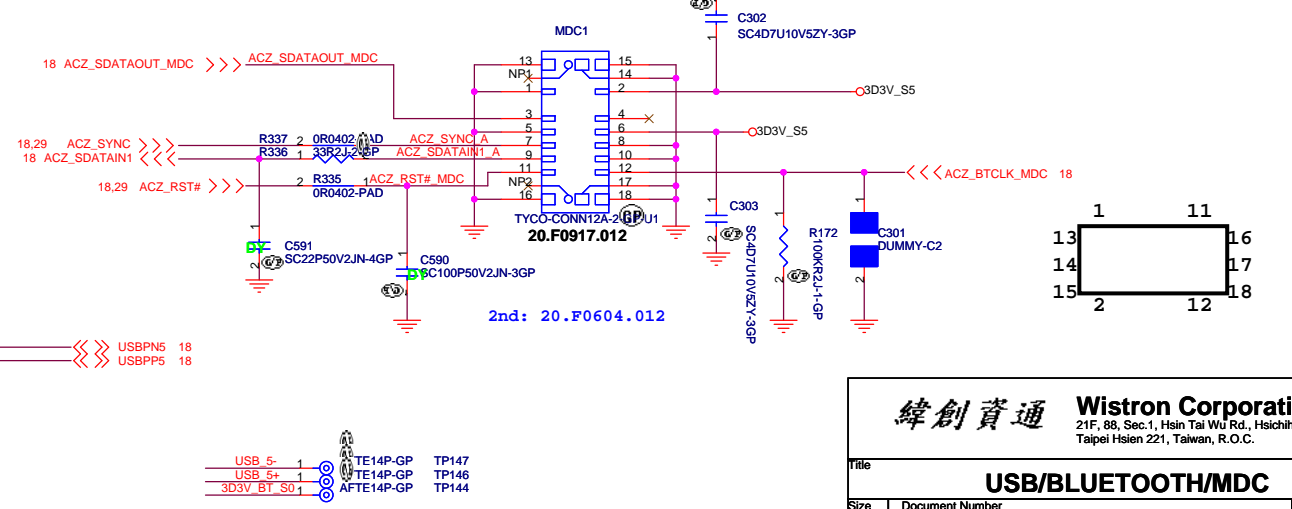


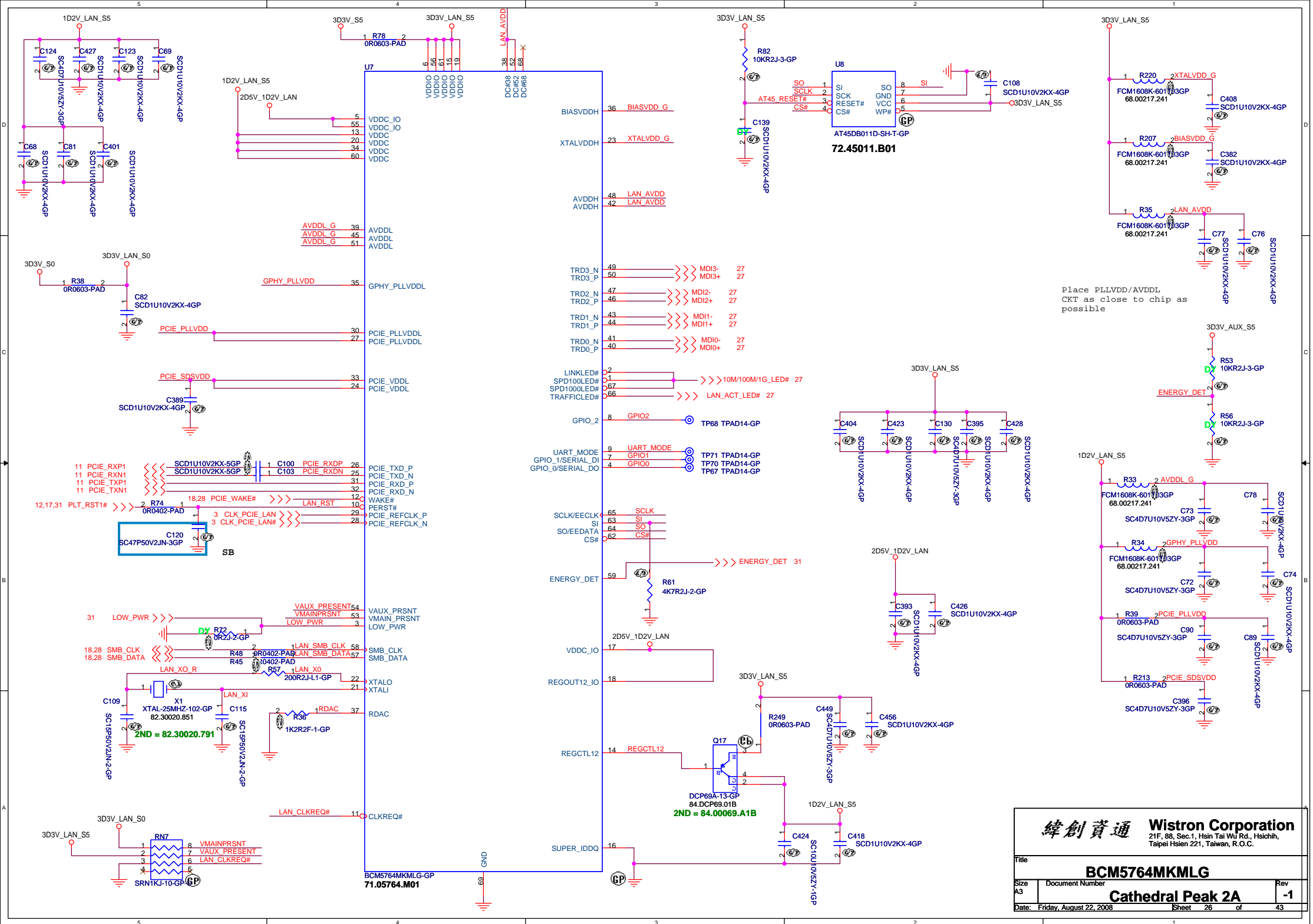
BLUETOOTH MODULE

1.5A / High Active Voltage 2V



MDC 1.5 CONN

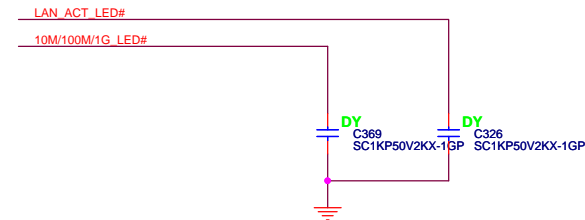




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1. route on bottom as differential pairs.
2. Tx+ /Tx- are pairs. Rx+ /Rx- are pairs.
3. No vias, No 90 degree bends.
4. pairs must be equal lengths.
5. 6mil trace width, 12mil separation.
6. 36mil between pairs and any other trace.
7. Must not cross ground moat, except RJ-45 moat.



The diagram shows the pinout for an RJ45-92-GP connector. The pins are numbered 1 through 15. The following table summarizes the connections shown in the diagram:

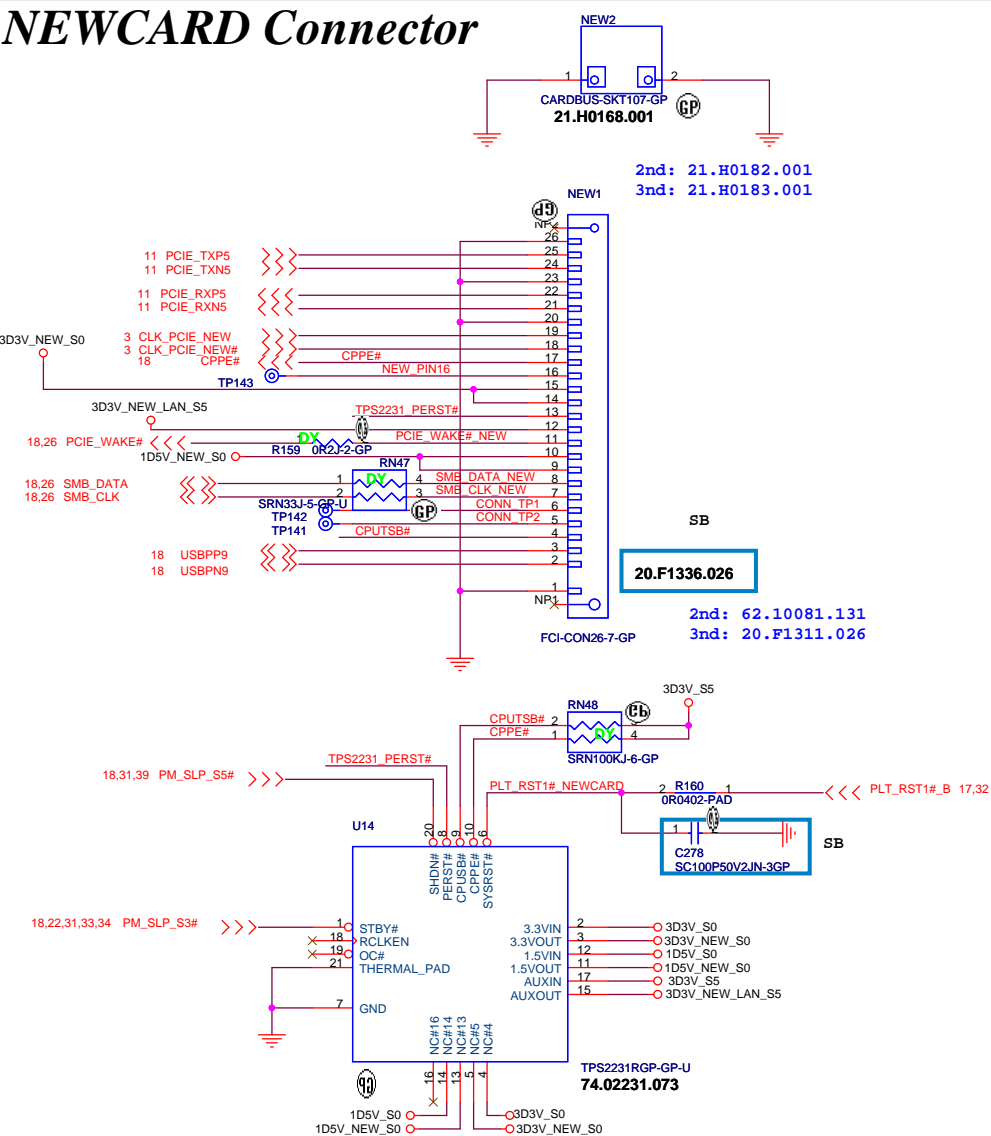
Pin Number	Signal / Label	Color / Note
1	RJ45_1	
2	RJ45_2	
3	RJ45_3	
4	RJ45_4	
5	RJ45_5	
6	RJ45_6	
7	RJ45_7	
8	RJ45_8	
9	CONN PWR	9:GREEN
10		
11		
12	CONN PWR2	
13		13:Orange
14		
15		

Additional labels in the diagram include: 26 10M/100M/1G_LED# (pointing to pins 1, 2, 3, 4, 5, 6, 7, 8), 26 LAN_ACT_LED# (pointing to pins 12, 13, 14, 15), and a ground symbol connected to pin 15. The connector is labeled RJ45-92-GP and SA.

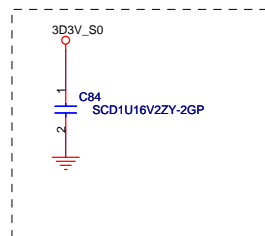
LAN Data: Yellow(13), when LAN is transferring data.

[illegible]

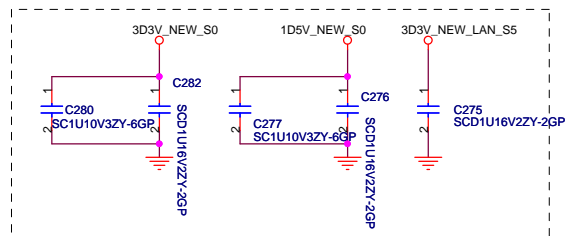
NEWCARD Connector



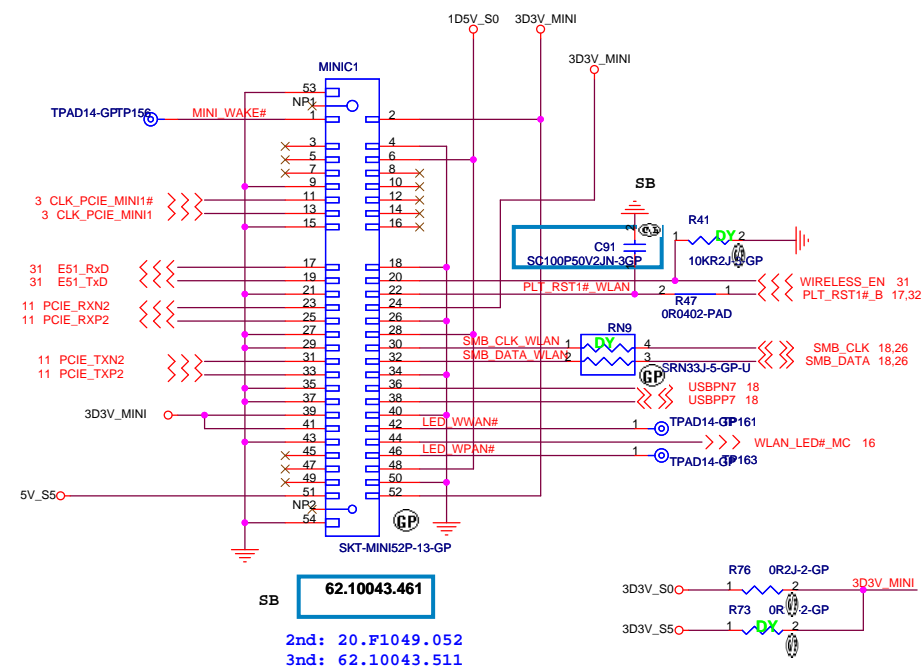
Place them Near to Chip



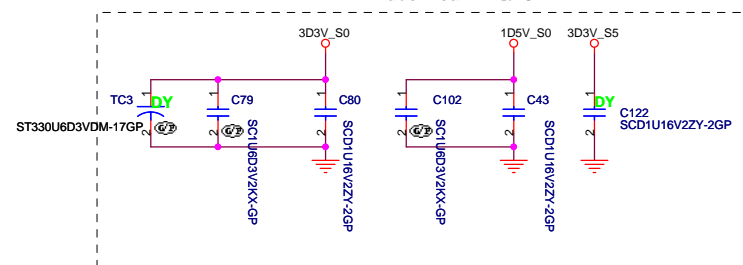
Place them Near to Connector

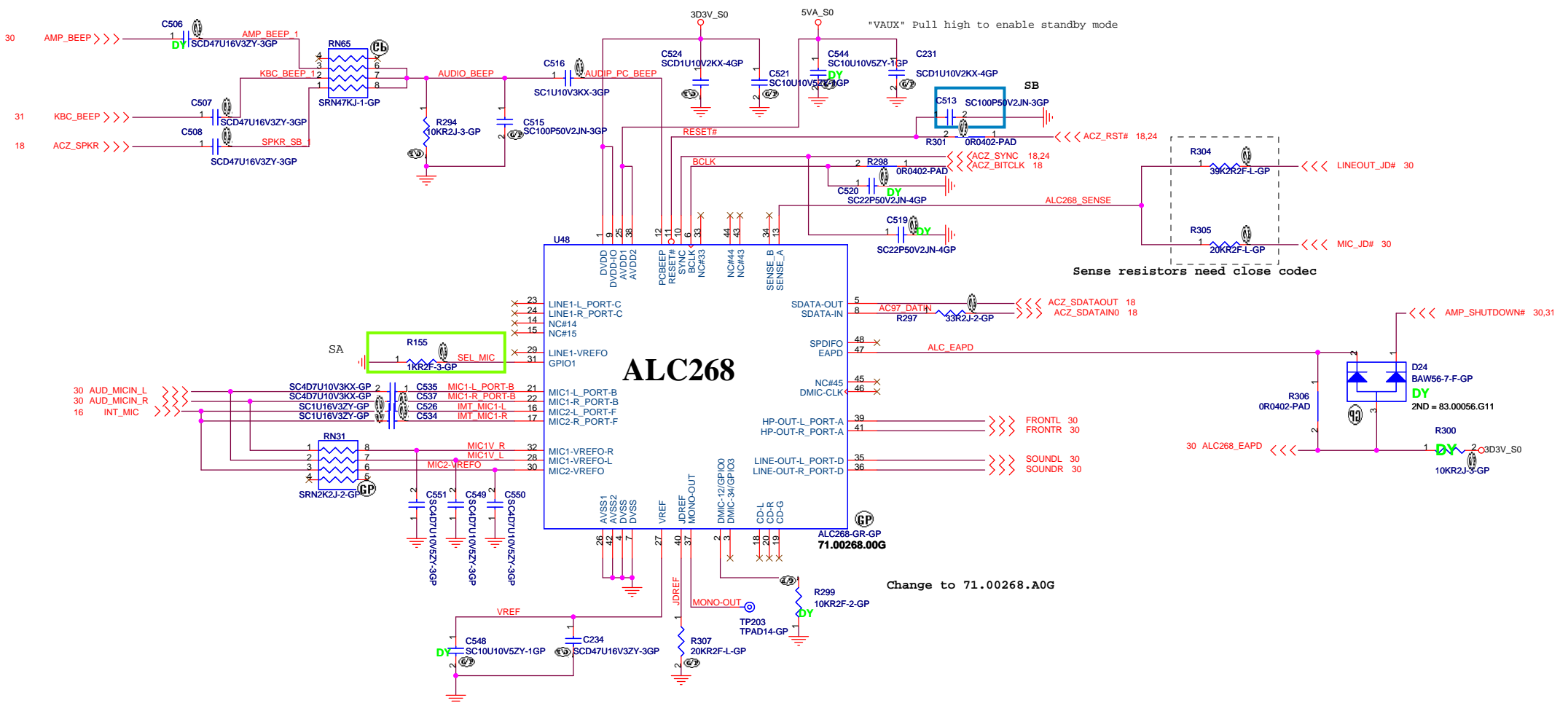
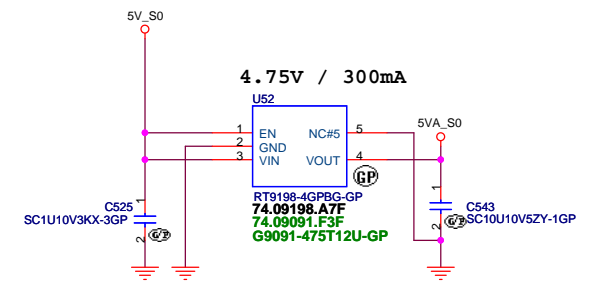


Mini Card Connector(WLAN)

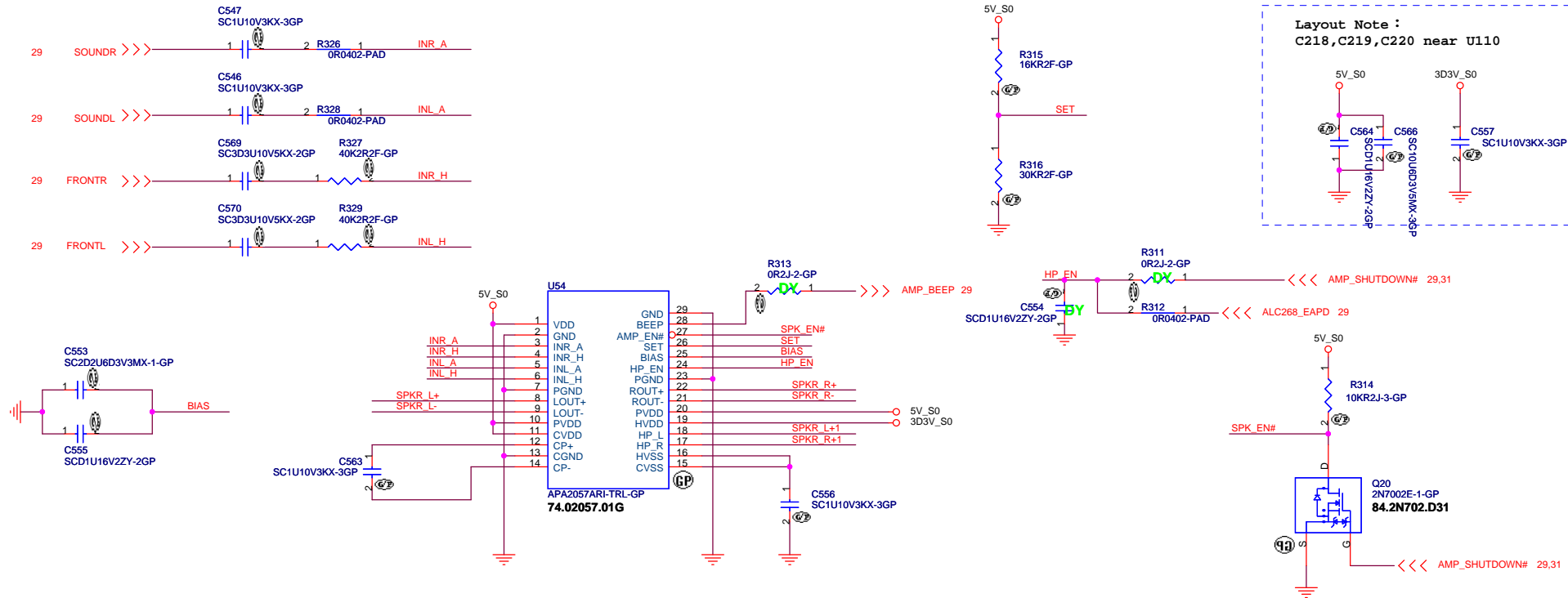


Place near MINIC1

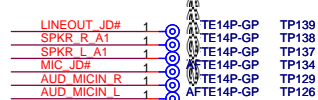
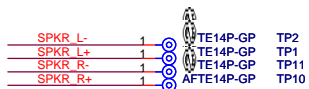
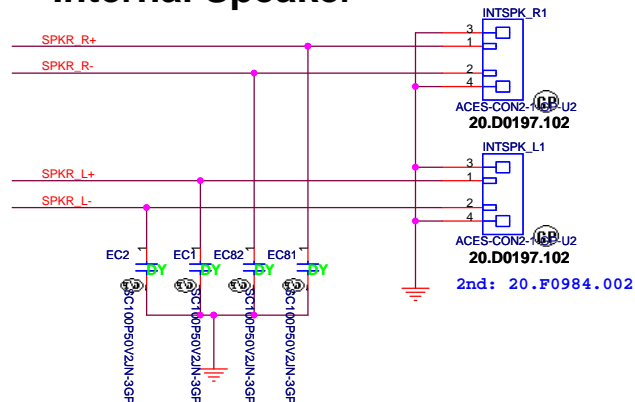




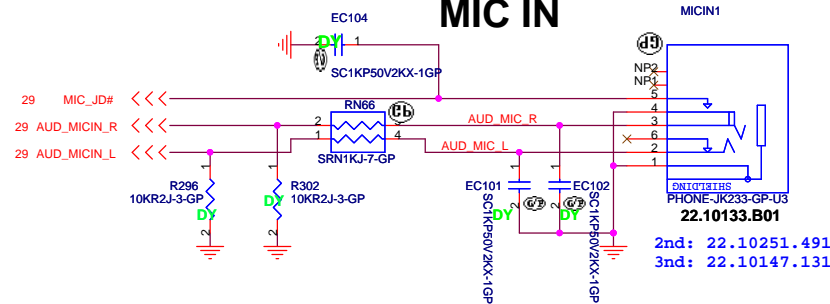
AUDIO OP AMPLIFIER



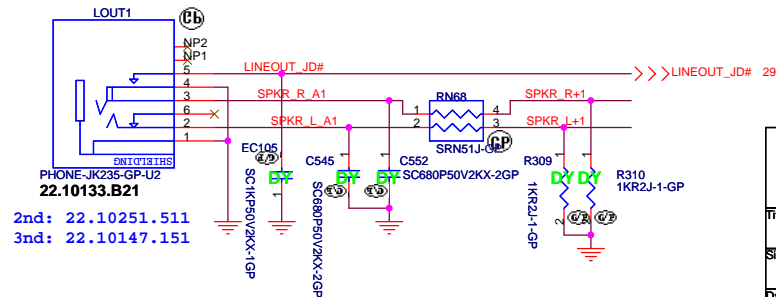
Internal Speaker



MIC IN



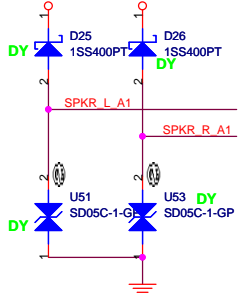
LINE OUT



Analog Int. Mic

remove to LED Board

For ESD

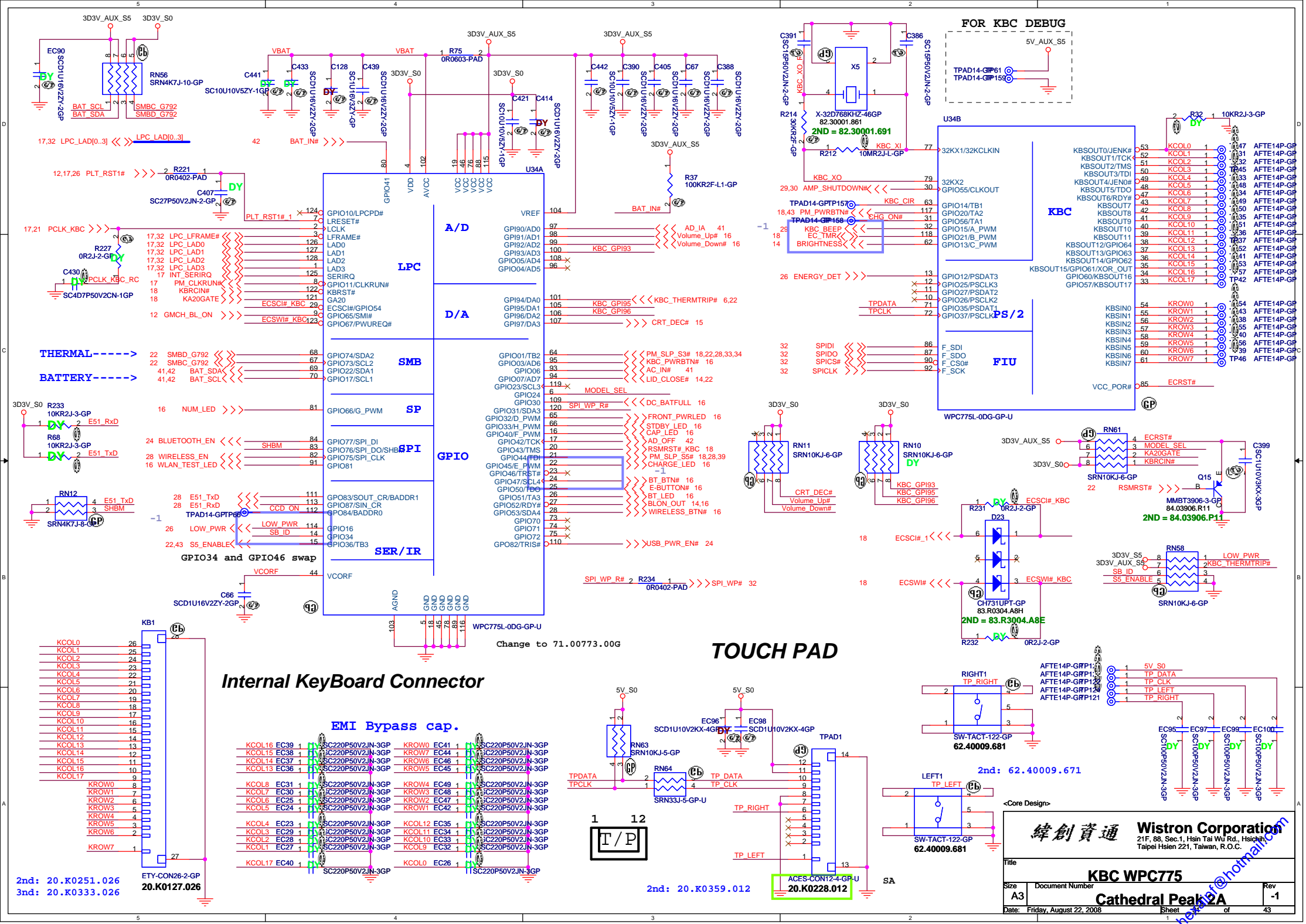


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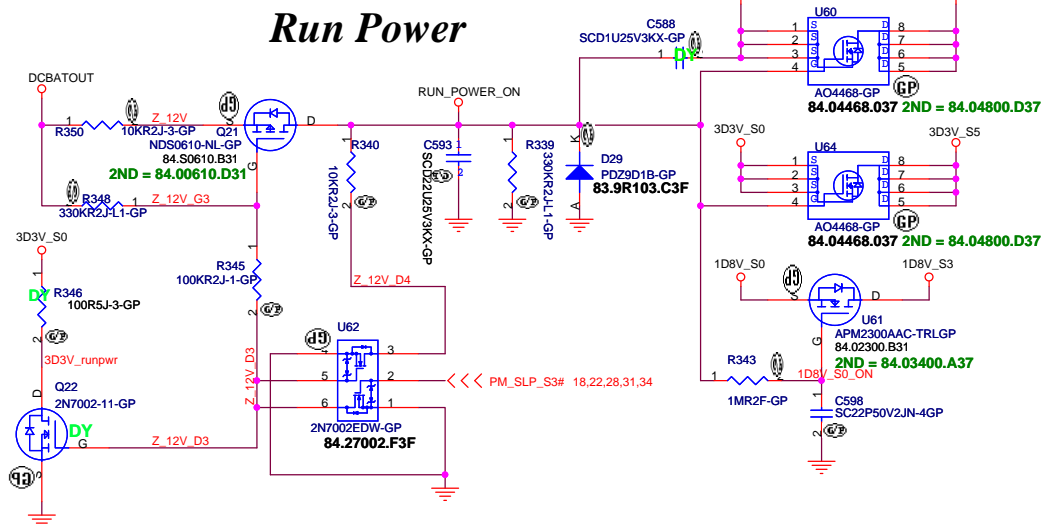
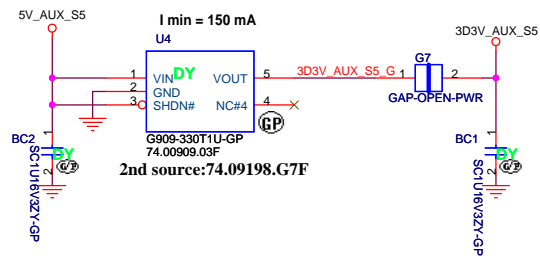
Wistron Corporation

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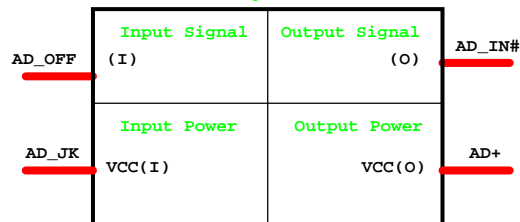
AUDIO AMP AND JACK			
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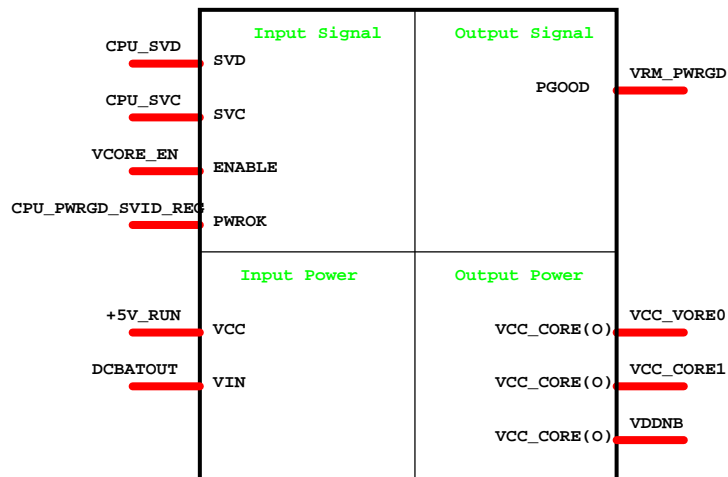
Aux Power 3D3V_AUX_S5



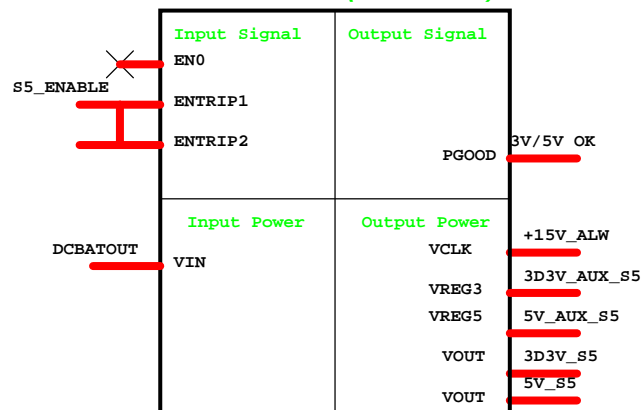
Adapter



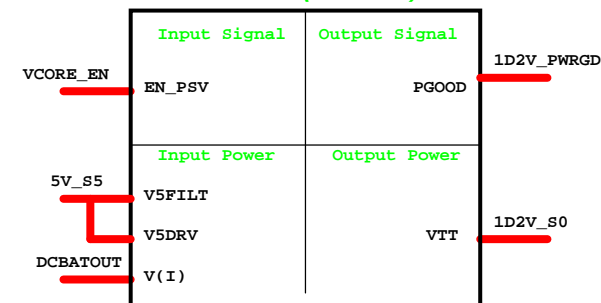
CPU_CORE ISL6265HRTZ



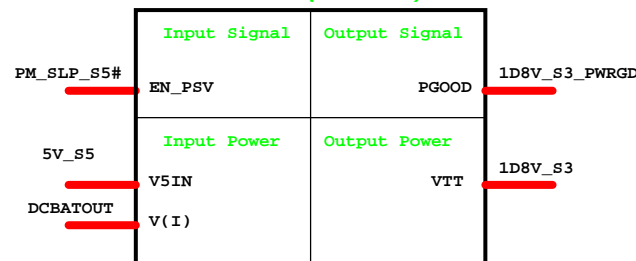
DCDC 5V/3D3V(TPS51125)



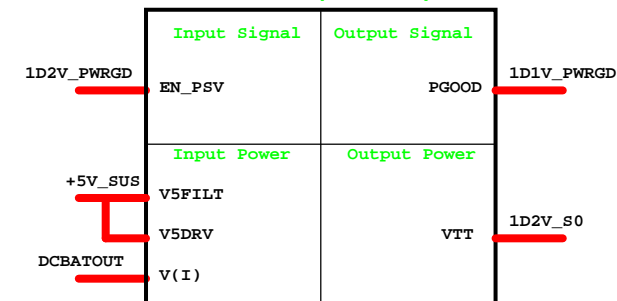
DCDC 1D2V(RT8202)



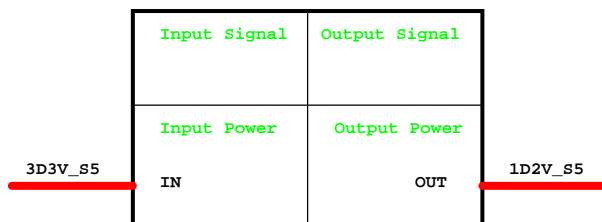
DCDC 1D8V(RT8202)



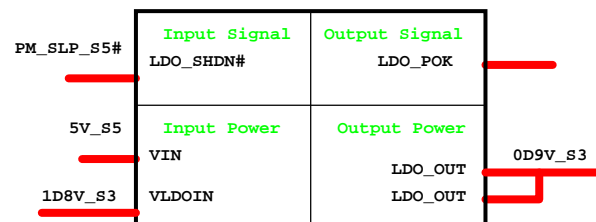
DCDC 1D1V(RT8202)



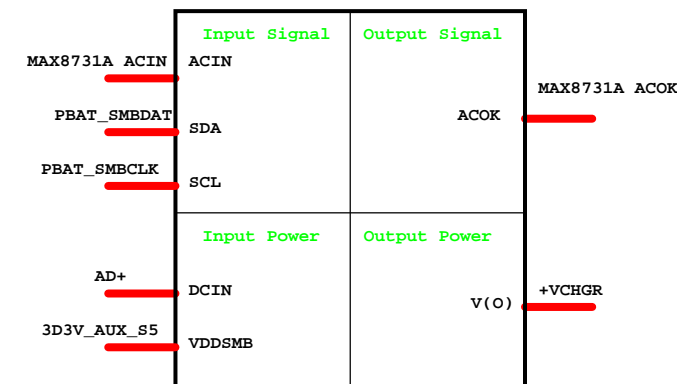
1D2V LDO G9161



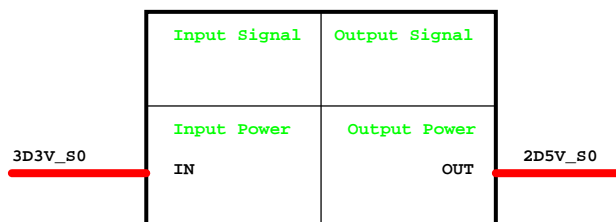
0D9V LDO RT9026



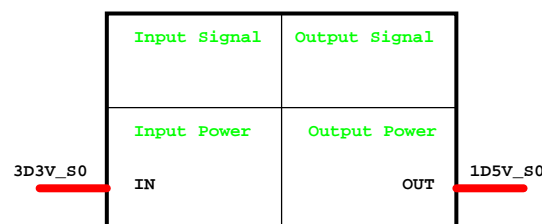
CHARGER MAX8731



2D5V LDO R9161



1D5V LDO G9571

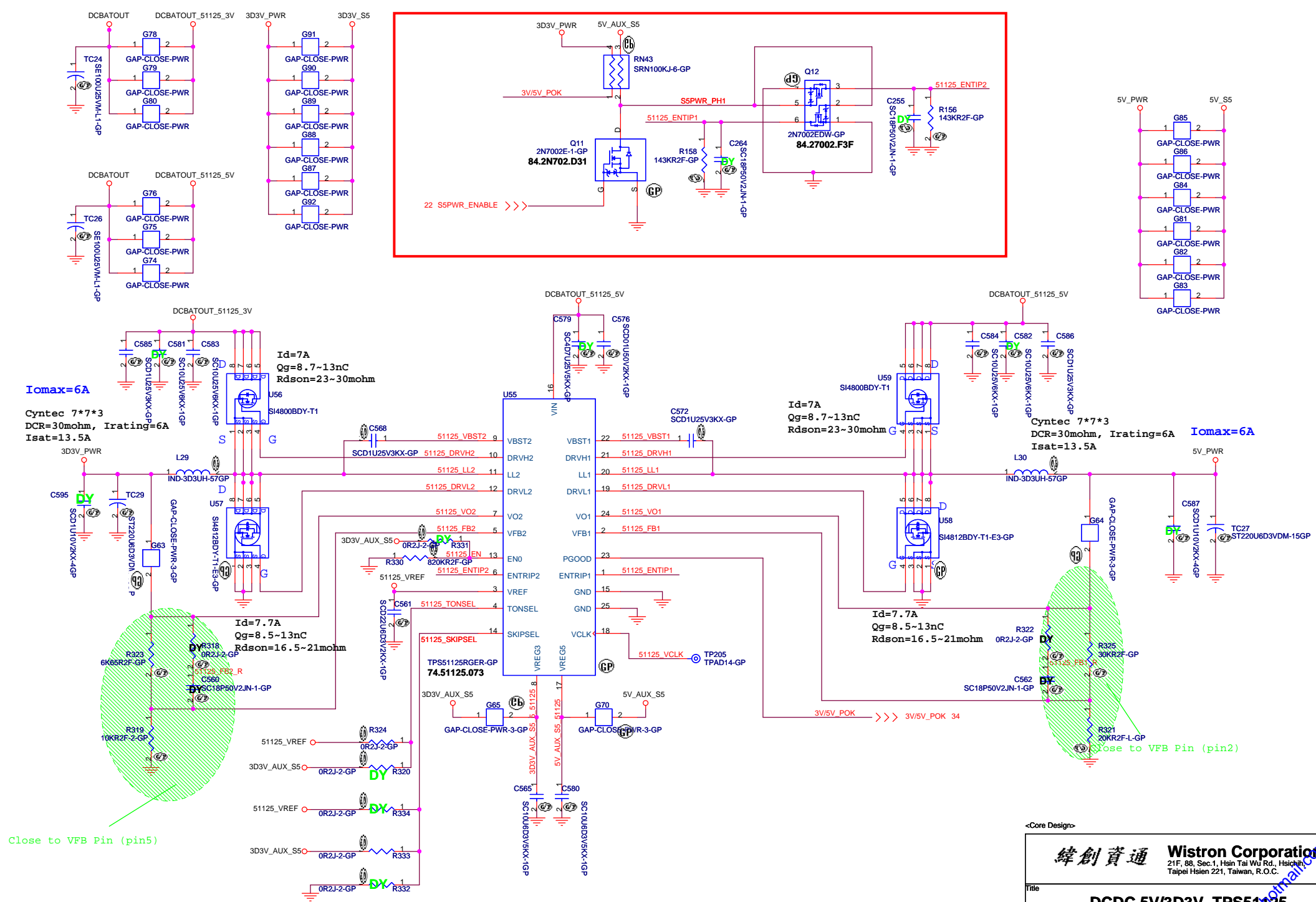


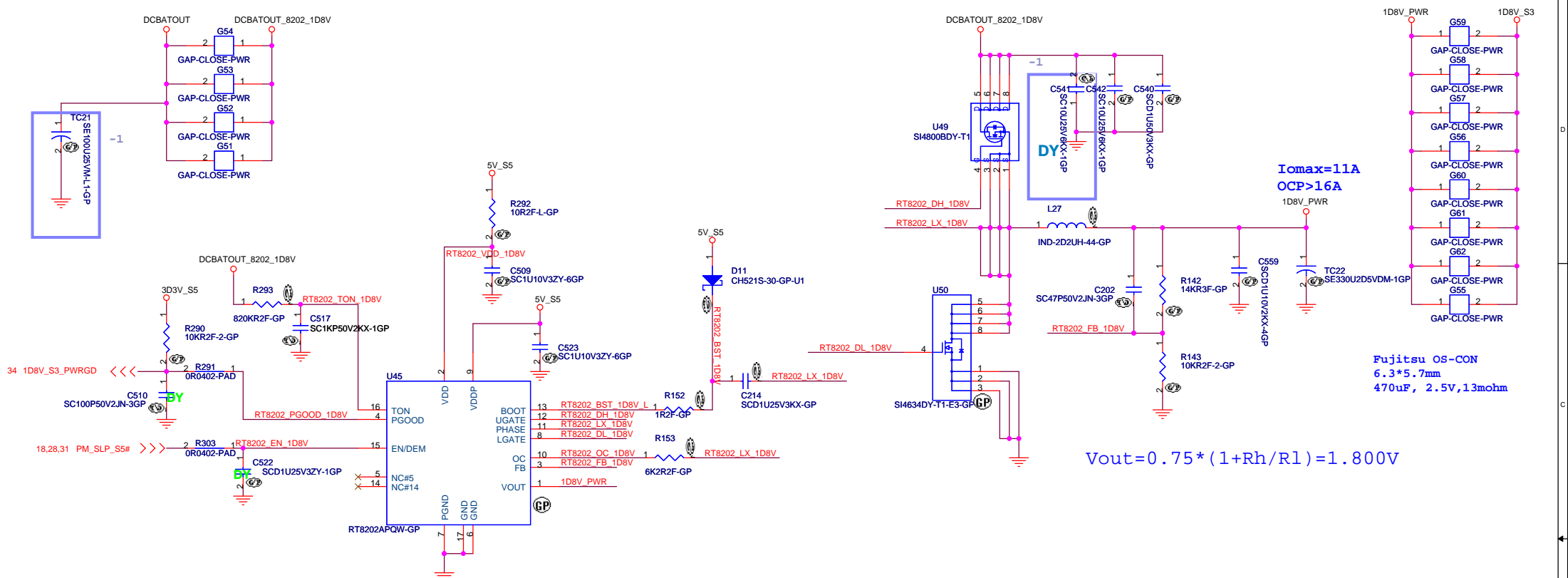
<Core Design>

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Taipei Hsien 221, Taiwan, R.O.C.

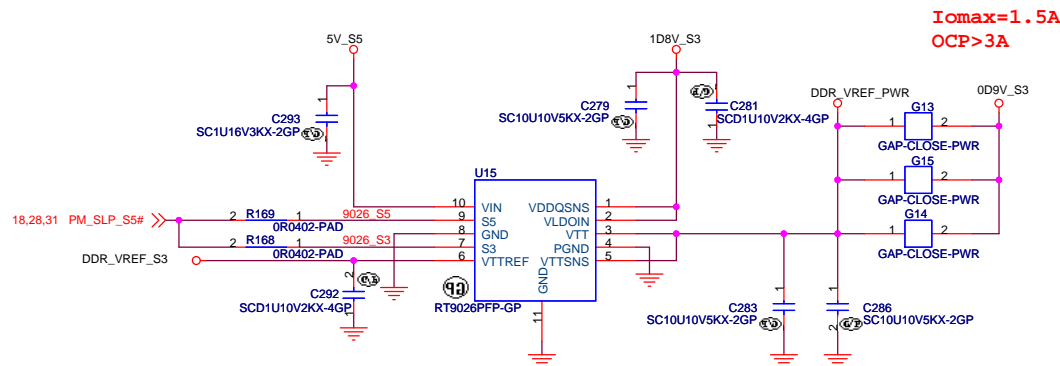
Title			Power Block Diagram
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A3			
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Cathedral Peak 2A -1

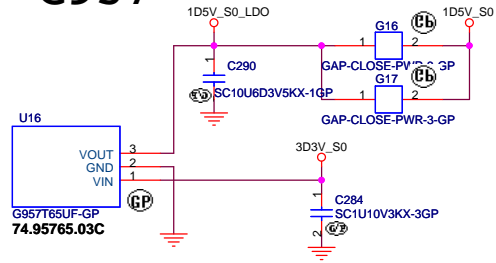




DDR_0.9V

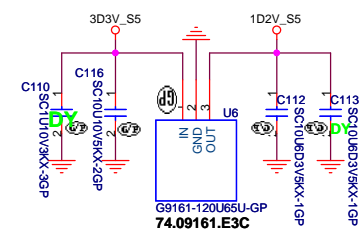


1D5V_S0 Iomax=1A **G957**



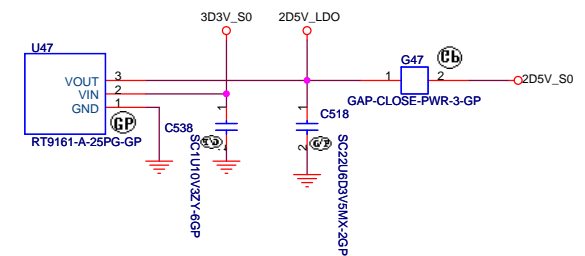
For MINI Card.NEW Card power SW

1D2V_S5 Iomax=400mA

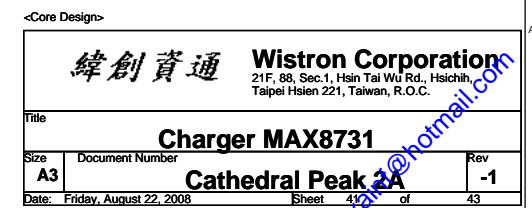


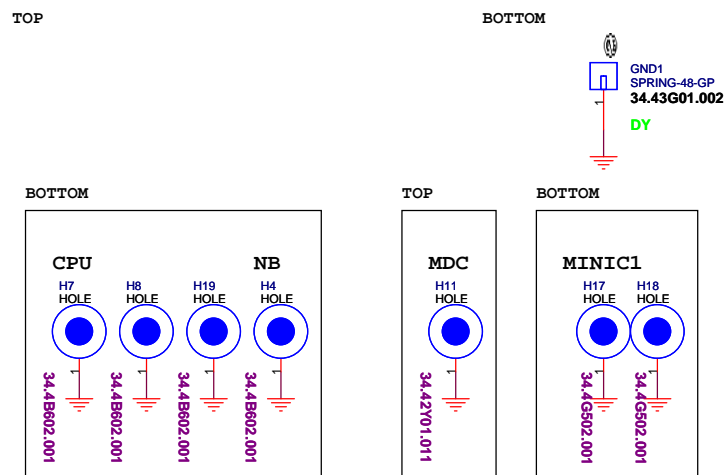
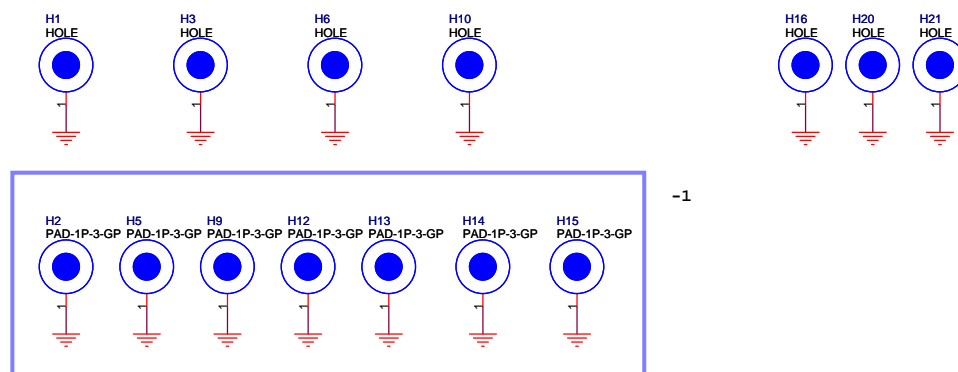
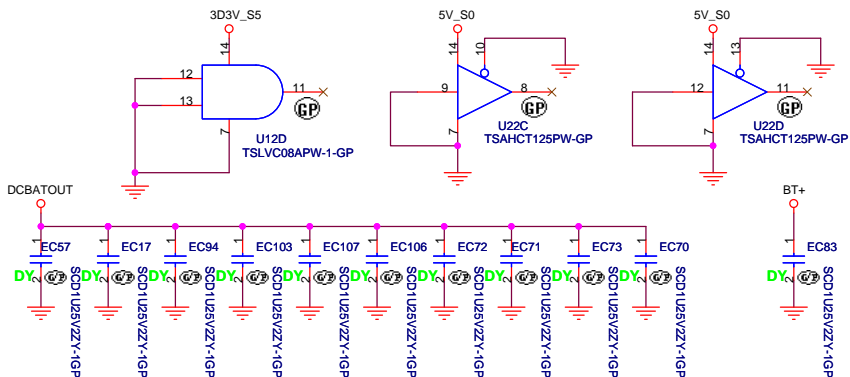
Place near to SB700

2D5V Iomax=0.2A



Place near to CPU





Check test point

3D3V_S0	TP140	TPAD14-GP
3D3V_AUX_S5	TP148	TPAD14-GP
3D3V_S5	TP145	TPAD14-GP
5V_S5	TP127	TPAD14-GP
18,31 PM_PWRBTN#	TP65	TPAD14-GP
6,17 CPU_PWRGD	TP188	TPAD14-GP
22,31 S5_ENABLE	TP160	TPAD14-GP
6,17 CPU_LDT_RST#	TP77	TPAD14-GP

Test Point 放在 Dimm Door 打開可量測處

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